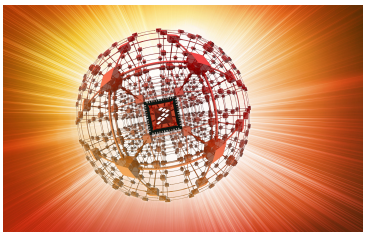
Document Number: MKMxxZxxCxx5
Rev. 7, 01/2014

# MKMxxZxxCxx5



## KM Family

Supports the following:
MKM14Z64CHH5, MKM14Z128CHH5, MKM33Z64CLH5, MKM33Z128CLH5, MKM33Z64CLL5, MKM33Z128CLL5, MKM34Z128CLL5

### Features

- Operating Characteristics
  - Voltage range: 1.71 V to 3.6 V (when Analog Front End (AFE) is not used)
  - Voltage range: 2.7 V to 3.6 V (when Analog Front End (AFE) is used)
  - iRTC battery supply voltage range: 1.71 to 3.6 V
  - Flash write voltage range: 1.71 to 3.6 V
  - Temperature range (ambient): -40°C to 85°C
- Performance
  - Up to 50 MHz ARM Cortex-M0+ core delivering 0.95 Dhrystone MIPS per MHz
- Memories and memory interfaces
  - 128/64 KB program flash memory. There is no FlexMemory on these devices
  - 16 KB of single access RAM
- Clocks
  - 1 to 32 MHz crystal oscillator
  - 32 kHz crystal oscillator
  - Multi-purpose clock generator
- System peripherals
  - Multiple low-power modes to provide power optimization based on application requirements
  - Memory protection unit with multi-master protection
  - 4-channel DMA controller, supporting up to 64 request sources
  - External watchdog monitor
  - Robust watchdog monitor
  - Low-leakage wakeup unit
  - Asynchronous wakeup unit
  - Peripheral Crossbar (allows internal signals to be connected to other on-chip modules)
- Security and integrity modules
  - Hardware programmable CRC module to support fast cyclic redundancy checks
  - Hardware random-number generator
  - 128-bit unique identification (ID) number per chip
- Human-machine interface
  - Segment LCD controller supporting up to 36 frontplanes and 8 backplanes or 40 frontplanes and 4 backplanes
  - General-purpose input/output which can acts as Rapid GPIO (single cycle access)
- Analog modules
  - 16-bit SAR ADC
  - 24-bit Analog Front End comprising of 24-bit Sigma Delta ADCs (after averaging)
  - Programmable Gain Amplifier (PGA with gains upto 32)
  - Two analog comparators (CMP) containing a 6-bit DAC and programmable reference input
  - 1.2V Voltage reference
- Timers
  - 4 channel Quad Timer with 16-bit counters
  - Periodic interrupt timers
  - 16-bit low-power timer
  - Independent Real Time Clock with calendaring and compensation
- Communication interfaces
  - One SPI module with FIFO support (supports 5V AMR operation)
  - One SPI module without FIFO (no AMR operation)
  - Two I2C modules with SMBus support
  - Two UART modules with ISO7816 support and Two UART without ISO 7816 support
  - Any one SCI can be used for IrDA operation. 5V AMR support on one SCI.

Freescale reserves the right to change the detail specifications as may be required to permit improvements in the design of its products.

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# 1 Ordering parts

## 1.1 Determining valid order-able parts

Valid order-able part numbers are provided on the web. To determine the order-able part numbers for this device, go to freescale.com and perform a part number search for the following device numbers:

- MKM13Z64CHH5
- MKM14Z64CHH5
- MKM14Z128CHH5
- MKM32Z64CLH5
- MKM33Z64CLH5
- MKM33Z128CLH5
- MKM32Z64CLL5
- MKM33Z64CLL5
- MKM33Z128CLL5
- MKM34Z128CLL5
- MKM38Z128CLL5

# 2 Part identification

## 2.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

## 2.2 Format

Part numbers for this device have the following format:

Q K M S R FFF T PP CC N

## 2.3 Fields

Following table lists the possible values for each field in the part number (not all combinations are valid):

| Field | Description | Values |
|---|---|---|
| Q | Qualification status | • M = Fully qualified, general market flow<br>• P = Pre-qualification (Proto) |
| K | Main family | • K = Kinetis |
| M | Sub family | • M1 = Metering only (No LCD support)<br>• M3 = Metering with LCD support |
| S | Number of Sigma Delta (SD) ADC | • 2 = 1 SD ADC with PGA and 1 SD ADC<br>• 3 = 2 SD ADC with PGA and 1 SD ADC<br>• 4 = 2 SD ADC with PGA and 2 SD ADC<br>• 8 = Same as '4'. |
| R | Silicon revision | • Z = Initial<br>• (Blank) = Main<br>• A = Revision after main |
| FFF | Program flash memory size | • 64 = 64 KB<br>• 128 = 128 KB |
| T | Temperature range (°C) | • C = –40 to 85 |
| PP | Package identifier | • HH = 44 LGA (5 mm x 5 mm)<br>• LH = 64 LQFP (10 mm x 10 mm)<br>• LL = 100 LQFP (14 mm x 14 mm) |
| CC | Maximum CPU frequency (MHz) | • 5 = 50 MHz |
| N | Packaging type | • R = Tape and reel<br>• (Blank) = Trays |

## 2.4 Example

This is an example part number:

- MKM34Z128CLL5

# 3 Terminology and guidelines

## 3.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

### 3.1.1 Example

This is an example of an operating requirement:

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $V_{DD}$ | 1.0 V core supply voltage | 0.9 | 1.1 | V |

## 3.2 Definition: Operating behavior

An *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

### 3.2.1 Example

This is an example of an operating behavior:

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $I_{WP}$ | Digital I/O weak pullup/ pulldown current | 10 | 130 | μA |

## 3.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

### 3.3.1 Example

This is an example of an attribute:

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| CIN_D | Input capacitance: digital pins | — | 7 | pF |

## 3.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

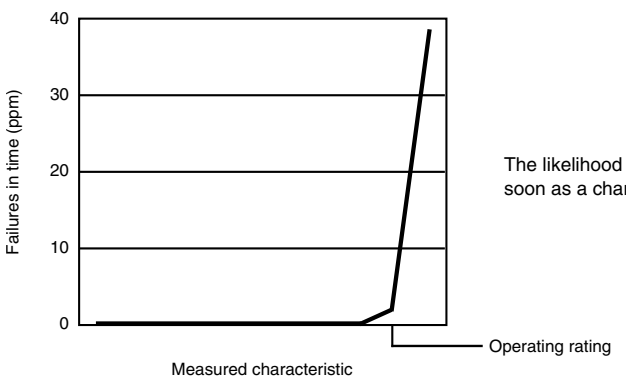
- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

### 3.4.1 Example

This is an example of an operating rating:

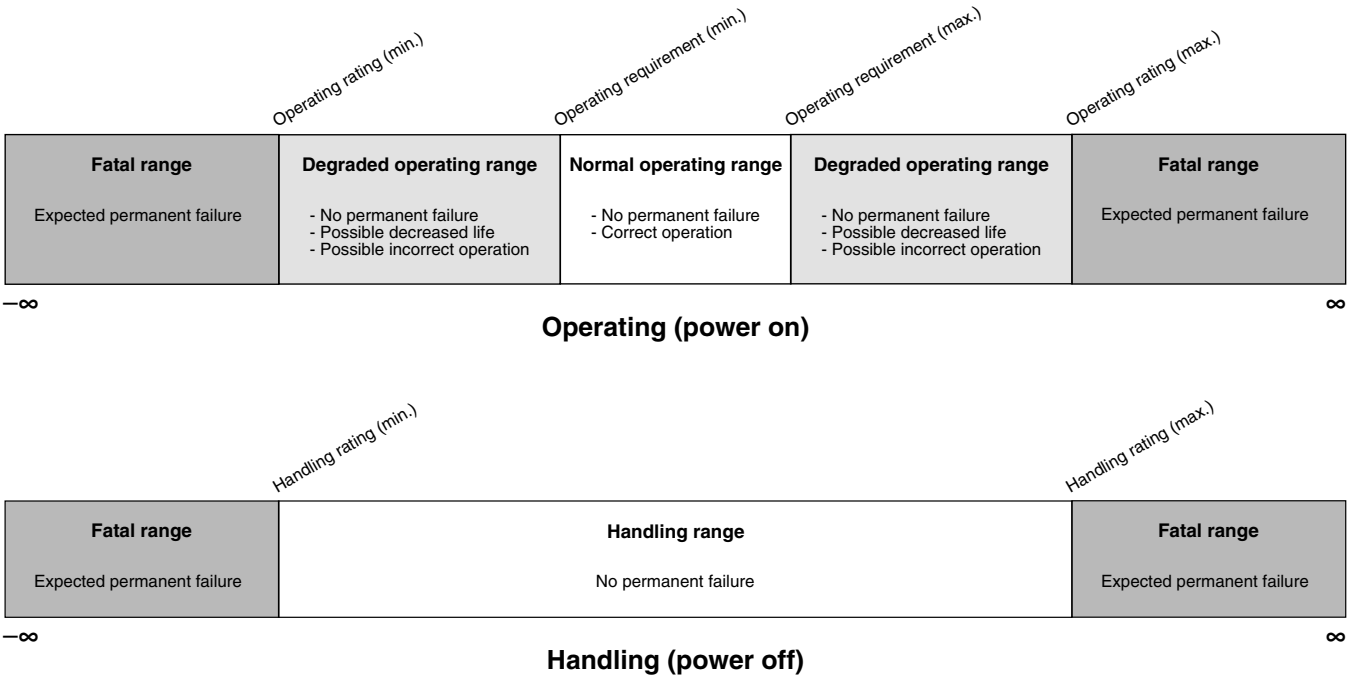
| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $V_{DD}$ | 1.0 V core supply voltage | –0.3 | 1.2 | V |

## 3.5 Result of exceeding a rating




The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings.

## 3.6 Relationship between ratings and operating requirements




## 3.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

## 3.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

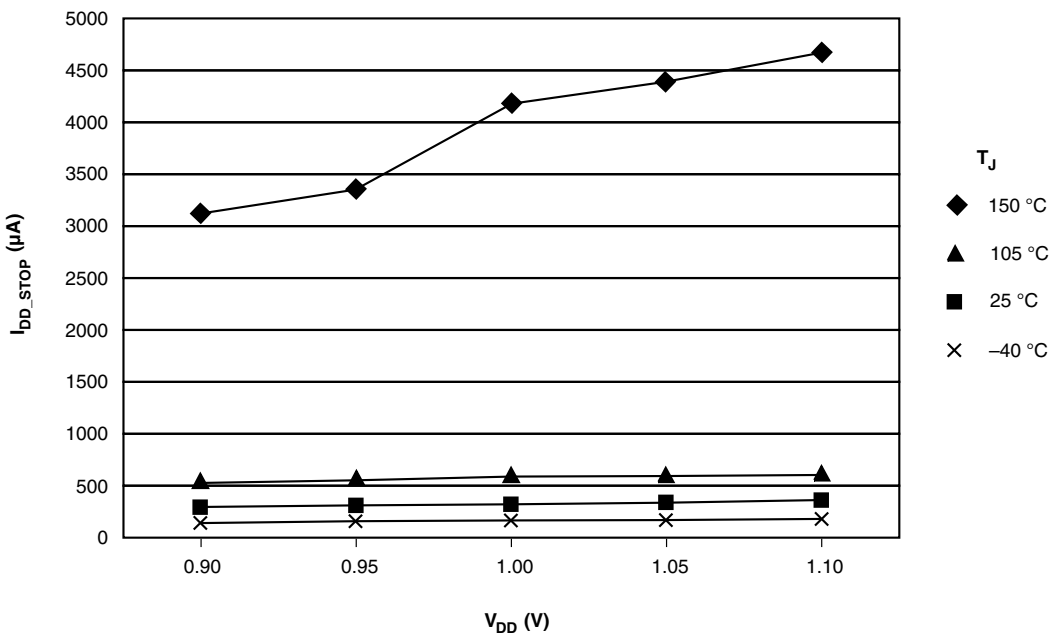
### 3.8.1 Example 1

This is an example of an operating behavior that includes a typical value:

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|
| $I_{WP}$ | Digital I/O weak pullup/pulldown current | 10 | 70 | 130 | μA |

### 3.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:




## 3.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

| Symbol | Description | Value | Unit |
|---|---|---|---|
| $T_A$ | Ambient temperature | 25 | °C |
| $V_{DD}$ | 3.3 V supply voltage | 3.3 | V |

# 4 Ratings

## 4.1 Thermal handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $T_{STG}$ | Storage temperature | –55 | 150 | °C | 1 |
| $T_{SDR}$ | Solder temperature, lead-free | — | 260 | °C | 2 |

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

## 4.2 Moisture handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| MSL | Moisture sensitivity level | — | 3 | — | 1 |

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

## 4.3 ESD handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{HBM}$ | Electrostatic discharge voltage, human body model (All pins except RESET pin) | -4000 | +4000 | V | 1 |
| | Electrostatic discharge voltage, human body model (RESET pin only) | -2500 | +2500 | V | 1 |
| $V_{CDM}$ | Electrostatic discharge voltage, charged-device model (for corner pins) | -750 | +750 | V | 2 |
| $V_{CDM}$ | Electrostatic discharge voltage, charged-device model | -500 | +500 | V | 3 |
| $V_{PESD}$ | Powered ESD voltage | -6000 | +6000 | V | |
| $I_{LAT}$ | Latch-up current at ambient temperature of 105°C | -100 | +100 | mA | |

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.
3. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.

## 4.4 Voltage and current operating ratings

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $V_{DD}$ | Digital supply voltage | –0.3 | 3.6 | V |
| $V_{DIO}$ | Digital input voltage (except $\overline{RESET}$, EXTAL, and XTAL) | –0.3 | $V_{DD}$ + 0.3 | V |
| $V_{DTamper}$ | Tamper input voltage | –0.3 | $V_{BAT}$ + 0.3 | V |
| $V_{AIO}$ | Analog[1], $\overline{RESET}$, EXTAL, and XTAL input voltage | –0.3 | $V_{DD}$ + 0.3 | V |
| $I_D$ | Instantaneous maximum current single pin limit (applies to all port pins) | –25 | 25 | mA |
| $V_{DDA}$ | Analog supply voltage | $V_{DD}$ – 0.3 | $V_{DD}$ + 0.3 | V |
| $V_{BAT}$ | RTC battery supply voltage | –0.3 | 3.6 | V |

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

# 5 General

## 5.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.

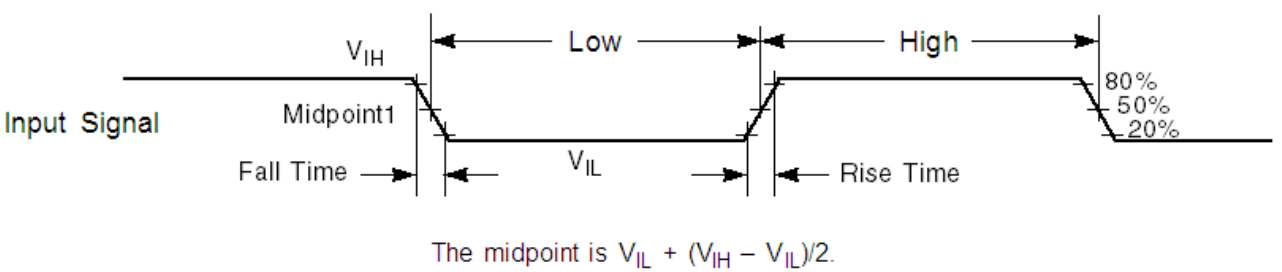



**Figure 1. Input signal measurement reference**

## 5.2 Nonswitching electrical specifications

## 5.2.1 Voltage and current operating requirements

### Table 1. Voltage and current operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{DD}$ | Supply voltage when AFE is operational | 2.7 | 3.6 | V | |
| | Supply voltage when AFE is NOT operational | 1.71 | 3.6 | V | |
| $V_{DDA}$ | Analog supply voltage | 2.7 | 3.6 | V | |
| $V_{DD} – V_{DDA}$ | $V_{DD}$-to-$V_{DDA}$ differential voltage | –0.1 | 0.1 | V | |
| $V_{SS} – V_{SSA}$ | $V_{SS}$-to-$V_{SSA}$ differential voltage | –0.1 | 0.1 | V | |
| $V_{BAT}$ | RTC battery supply voltage | 1.71 | 3.6 | V | 1 |
| $V_{IH}$ | Input high voltage<br>• $2.7 V \le V_{DD} \le 3.6 V$<br>• $1.7 V \le V_{DD} \le 2.7 V$ | <br>$0.7 \times V_{DD}$<br>$0.75 \times V_{DD}$ | <br>—<br>— | <br>V<br>V | |
| $V_{IL}$ | Input low voltage<br>• $2.7 V \le V_{DD} \le 3.6 V$<br>• $1.7 V \le V_{DD} \le 2.7 V$ | <br>—<br>— | <br>$0.35 \times V_{DD}$<br>$0.3 \times V_{DD}$ | <br>V<br>V | |
| $V_{HYS}$ | Input hysteresis | $0.06 \times V_{DD}$ | — | V | |
| $I_{ICDIO}$ | Digital pin negative DC injection current — single pin<br>• $V_{IN} < V_{SS}$-0.3V | -5 | — | mA | |
| $I_{ICAIO}$ | Analog[2], EXTAL, and XTAL pin DC injection current — single pin<br>• $V_{IN} < V_{SS}$-0.3V (Negative current injection)<br>• $V_{IN} > V_{DD}$+0.3V (Positive current injection) | <br>-3<br>— | <br>—<br>+3 | mA | |
| $I_{ICcont}$ | Contiguous pin DC injection current —regional limit, includes sum of negative injection currents or sum of positive injection currents of 16 contiguous pins<br>• Negative current injection<br>• Positive current injection | <br>-25<br>— | <br>—<br>+25 | mA | |
| $V_{RFVBAT}$ | $V_{BAT}$ voltage required to retain the VBAT register file | $V_{POR_VBAT}$ | — | V | |

1. $V_{BAT}$ always needs to be there for the chip to be operational.
2. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

## 5.2.2 LVD and POR operating requirements

### Table 2. $V_{DD}$ supply LVD and POR operating requirements

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $V_{POR}$ | Falling VDD POR detect voltage | 0.8 | 1.1 | 1.5 | V | |
| $V_{LVDH}$ | Falling low-voltage detect threshold — high range (LVDV=01) | 2.48 | 2.56 | 2.64 | V | |

*Table continues on the next page...*

**Table 2. $V_{DD}$ supply LVD and POR operating requirements (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| | Low-voltage warning thresholds — high range | | | | | 1 |
| $V_{LVW1H}$ | • Level 1 falling (LVWV=00) | 2.62 | 2.70 | 2.78 | V | |
| $V_{LVW2H}$ | • Level 2 falling (LVWV=01) | 2.72 | 2.80 | 2.88 | V | |
| $V_{LVW3H}$ | • Level 3 falling (LVWV=10) | 2.82 | 2.90 | 2.98 | V | |
| $V_{LVW4H}$ | • Level 4 falling (LVWV=11) | 2.92 | 3.00 | 3.08 | V | |
| $V_{HYSH}$ | Low-voltage inhibit reset/recover hysteresis — high range | — | 80 | — | mV | |
| $V_{LVDL}$ | Falling low-voltage detect threshold — low range (LVDV=00) | 1.54 | 1.60 | 1.66 | V | |
| | Low-voltage warning thresholds — low range | | | | | 1 |
| $V_{LVW1L}$ | • Level 1 falling (LVWV=00) | 1.74 | 1.80 | 1.86 | V | |
| $V_{LVW2L}$ | • Level 2 falling (LVWV=01) | 1.84 | 1.90 | 1.96 | V | |
| $V_{LVW3L}$ | • Level 3 falling (LVWV=10) | 1.94 | 2.00 | 2.06 | V | |
| $V_{LVW4L}$ | • Level 4 falling (LVWV=11) | 2.04 | 2.10 | 2.16 | V | |
| $V_{HYSL}$ | Low-voltage inhibit reset/recover hysteresis — low range | — | 60 | — | mV | |
| $V_{BG}$ | Bandgap voltage reference | 0.97 | 1.00 | 1.03 | V | |
| $t_{LPO}$ | Internal low power oscillator period — factory trimmed | 900 | 1000 | 1100 | μs | |

1. Rising threshold is the sum of falling threshold and hysteresis voltage

**Table 3. VBAT power operating requirements**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $V_{POR_VBAT}$ | Falling VBAT supply POR detect voltage | 0.8 | 1.1 | 1.5 | V | |

## 5.2.3 Voltage and current operating behaviors

**Table 4. Voltage and current operating behaviors**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{OH}$ | Output high voltage — high-drive strength | | | | |
| | • 2.7 V ≤ $V_{DD}$ ≤ 3.6 V, $I_{OH}$ = 20 mA | $V_{DD}$ – 0.5 | — | V | |
| | • 1.71 V ≤ $V_{DD}$ ≤ 2.7 V, $I_{OH}$ = 10 mA | $V_{DD}$ – 0.5 | — | V | |
| | Output high voltage — low-drive strength | | | | |
| | • 2.7 V ≤ $V_{DD}$ ≤ 3.6 V, $I_{OH}$ = 5 mA | $V_{DD}$ – 0.5 | — | V | |
| | • 1.71 V ≤ $V_{DD}$ ≤ 2.7 V, $I_{OH}$ = 2.5 mA | $V_{DD}$ – 0.5 | — | V | |
| $I_{OHT}$ | Output high current total for all ports | — | 100 | mA | |

*Table continues on the next page...*

**Table 4. Voltage and current operating behaviors (continued)**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{OL}$ | Output low voltage — high-drive strength<br>• 2.7 V ≤ $V_{DD}$ ≤ 3.6 V, $I_{OL}$ = 20 mA<br>• 1.71 V ≤ $V_{DD}$ ≤ 2.7 V, $I_{OL}$ = 10 mA | <br>—<br>— | <br>0.5<br>0.5 | <br>V<br>V | |
| | Output low voltage — low-drive strength<br>• 2.7 V ≤ $V_{DD}$ ≤ 3.6 V, $I_{OL}$ = 5 mA<br>• 1.71 V ≤ $V_{DD}$ ≤ 2.7 V, $I_{OL}$ = 2.5 mA | <br>—<br>— | <br>0.5<br>0.5 | <br>V<br>V | |
| $I_{OLT}$ | Output low current total for all ports | — | 100 | mA | |
| $I_{OZ}$ | Hi-Z (off-state) leakage current (per pin) | — | 1 | μA | |
| $R_{PU}$ | Internal pullup resistors | 30 | 60 | kΩ | 1, |
| $R_{PD}$ | Internal pulldown resistors | 30 | 60 | kΩ | 2 |

1. Measured at Vinput = $V_{SS}$
2. Measured at Vinput = $V_{DD}$

## 5.2.4 Power mode transition operating behaviors

All specifications except $t_{POR}$, and VLLSx→RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 50 MHz
- Bus clock = 25 MHz
- Flash clock = 25 MHz
- Temp: -40 °C, 25 °C, and 85 °C
- $V_{DD}$: 1.71 V, 3.3 V, and 3.6 V

**Table 5. Power mode transition operating behaviors**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $t_{POR}$ | After a POR event, amount of time from the point $V_{DD}$ reaches 1.71 V to execute the first instruction across the operating temperature range of the chip. | 563 | 659 | μs | 1 |
| | • VLLS0 → RUN | — | 372 | μs | |
| | • VLLS1 → RUN | — | 372 | μs | |
| | • VLLS2 → RUN | — | 273 | μs | |
| | • VLLS3 → RUN | — | 273 | μs | |
| | • VLPS → RUN | — | 5.0 | μs | |

*Table continues on the next page...*

**Table 5. Power mode transition operating behaviors (continued)**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| | • STOP → RUN | — | 5.0 | μs | |

1. Normal boot (FTFA_OPT[LPBOOT]=1)

## 5.2.5 Power consumption operating behaviors

**Table 6. Power consumption operating behaviors**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $I_{DDA}$ | Analog supply current | — | — | See note | mA | 1 |
| $I_{DD_RUN}$ | Run mode current — all peripheral clocks disabled, code executing from flash<br>• @ 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br><br><br>—<br>—<br>— | <br><br><br>6.17<br>6.39<br>6.93 | <br><br><br>7.1<br>6.7<br>8.3 | <br><br><br>mA<br>mA<br>mA | 2 |
| $I_{DD_RUN}$ | Run mode current — all peripheral clocks enabled, code executing from flash<br>• @ 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br><br><br>—<br>—<br>— | <br><br><br>8.24<br>8.26<br>9.00 | <br><br><br>10.4<br>9.8<br>11.5 | <br><br><br>mA<br>mA<br>mA | 2 |
| $I_{DD_WAIT}$ | Wait mode high frequency current at 3.0 V— all peripheral clocks disabled and Flash is not in low-power<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>3.95 | <br>4.65<br>4.4<br>6 | <br>mA<br>mA<br>mA | 2 |
| $I_{DD_WAIT}$ | Wait mode high frequency current at 3.0 V— all peripheral clocks disabled and Flash disabled (put in low-power)<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>3.81 | <br>4.4<br>4.2<br>5.8 | <br>mA<br>mA<br>mA | 2, 3 |
| $I_{DD_VLPR}$ | Very-low-power run mode current at 3.0 V — all peripheral clocks disabled<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>248.8<br>245.30<br>535.40 | <br>500<br>470<br>1800 | <br>μA<br>μA<br>μA | 4 |
| $I_{DD_VLPR}$ | Very-low-power run mode current at 3.0 V — all peripheral clocks enabled<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>343.4<br>336.62<br>626.18 | <br>530<br>500<br>2000 | <br>μA<br>μA<br>μA | 5 |

*Table continues on the next page...*

## Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $I_{DD_VLPW}$ | Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>162<br>158.50<br>446.94 | <br>350<br>330<br>1700 | <br>μA<br>μA<br>μA | 6 |
| $I_{DD_STOP}$ | Stop mode current at 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>311.90<br>364<br>645.13 | <br>730<br>700<br>2250 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLPS}$ | Very-low-power stop mode current at 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>8.56 | <br>46<br>44<br>1500 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLLS3}$ | Very low-leakage stop mode 3 current at 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>1.98 | <br>3.5<br>3.3<br>85 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLLS2}$ | Very low-leakage stop mode 2 current at 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>1.24 | <br>2.6<br>2.5<br>59.5 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLLS1}$ | Very low-leakage stop mode 1 current at 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>0.89 | <br>1.7<br>1.6<br>38.8 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLLS0}$ | Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit disabled<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>0.35 | <br>0.67<br>0.64<br>38 | <br>μA<br>μA<br>μA | |
| $I_{DD_VLLS0}$ | Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit enabled<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>0.472 | <br>0.76<br>0.72<br>38.4 | <br>μA<br>μA<br>μA | |
| $I_{DD_VBAT}$ | Average current with RTC and 32 kHz disabled at 3.0 V and VDD is OFF<br>• 25 °C<br>• -40 °C<br>• 105 °C | <br>—<br>—<br>— | <br>0.3 | <br>1<br>0.95<br>15 | <br>μA<br>μA<br>μA | |

*Table continues on the next page...*

### Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $I_{DD_VBAT}$ | Average current when VDD is OFF and LFSR and Tamper clocks set to 2 Hz.<br>• @ 3.0 V<br>• 25 °C<br>• -40 °C<br>• 105 °C | — | 1.3 [7] | 3<br>2.5<br>16 | μA<br>μA<br>μA | 8, 9 |

1. See AFE specification for IDDA.
2. 50 MHz core and system clock, 25 MHz bus clock, and 25 MHz flash clock. MCG configured for FBE mode. All peripheral clocks disabled.
3. Should be reduced by 500 μA.
4. 2 MHz core, system, bus clock, and 1 MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. Code executing while (1) loop from flash.
5. 2 MHz core, system and bus clock, and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing while (1) loop from flash.
6. 2 MHz core, system and bus clock, and 1 MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. No flash accesses; some activity on DMA & RAM assumed.
7. Current consumption will vary with number of CPU accesses done and is dependent on the frequency of the accesses and frequency of bus clock. Number of CPU accesses should be optimized to get optimal current value.
8. Includes 32 kHz oscillator current and RTC operation.
9. An external power switch for VBAT should be present on board to have better battery life and keep VBAT pin powered in all conditions. There is no internal power switch in RTC.

## 5.2.6 EMC radiated emissions operating behaviors

### Table 7. EMC radiated emissions operating behaviors

| Symbol | Description | Frequency band (MHz) | Typ. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{RE1}$ | Radiated emissions voltage, band 1 | 0.15–50 | 14 | dBμV | 1, 2 |
| $V_{RE2}$ | Radiated emissions voltage, band 2 | 50–150 | 16 | dBμV | |
| $V_{RE3}$ | Radiated emissions voltage, band 3 | 150–500 | 12 | dBμV | |
| $V_{RE4}$ | Radiated emissions voltage, band 4 | 500–1000 | 5 | dBμV | |
| $V_{RE_IEC}$ | IEC level | 0.15–1000 | M | — | 2, 3 |

1. Determined according to IEC Standard 61967-1, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 1: General Conditions and Definitions* and IEC Standard 61967-2, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 2: Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*. Measurements were made while the microcontroller was running basic application code. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.
2. $V_{DD}$ = 3.3 V, $T_A$ = 25 °C, $f_{OSC}$ = 10 MHz (crystal), $f_{SYS}$ = 50 MHz, $f_{BUS}$ = 25 MHz
3. Specified according to Annex D of IEC Standard 61967-2, *Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*

### 5.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to www.freescale.com.
2. Perform a keyword search for “EMC design.”

### 5.2.8 Capacitance attributes

**Table 8. Capacitance attributes**

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $C_{IN_A}$ | Input capacitance: analog pins | — | 7 | pF |
| $C_{IN_D}$ | Input capacitance: digital pins | — | 7 | pF |
| $C_{IN_D_io60}$ | Input capacitance: fast digital pins | — | 9 | pF |

## 5.3 Switching specifications

### 5.3.1 Device clock specifications

**Table 9. Device clock specifications**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| Normal run mode | | | | | |
| $f_{SYS}$ | System and core clock | | 50 | MHz | |
| $f_{BUS}$ | Bus clock | | 25 | MHz | |
| $f_{FLASH}$ | Flash clock | | 25 | MHz | |
| $f_{AFE}$ | AFE Modulator clock | | 6.5 | MHz | |
| VLPR mode[1] | | | | | |
| $f_{SYS}$ | System and core clock | | 2 | MHz | |
| $f_{BUS}$ | Bus clock | | 1 | MHz | |
| $f_{FLASH}$ | Flash clock | | 1 | MHz | |
| $f_{AFE}$ | AFE Modulator clock[2] | | 1.6 | MHz | |

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.
2. AFE working in low-power mode.

### 5.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, and $I^2C$ signals.

**Table 10. General switching specifications**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| | GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path | 1.5 | — | Bus clock cycles | 1 |
| | GPIO pin interrupt pulse width (digital glitch filter disabled) — Asynchronous path | 16 | — | ns | 2 |
| | External reset pulse width (digital glitch filter disabled) | 100 | — | ns | 2 |
| | Port rise and fall time—Low (All pins) and high drive (only PTC2) strength | | | | 3 |
| | • Slew disabled | | | | |
| | • $1.71 \le V_{DD} \le 2.7$ V | — | 8 | ns | |
| | • $2.7 \le V_{DD} \le 3.6$ V | — | 5 | ns | |
| | • Slew enabled | | | | |
| | • $1.71 \le V_{DD} \le 2.7$ V | — | 27 | ns | |
| | • $2.7 \le V_{DD} \le 3.6$ V | — | 16 | ns | |

1. The greater synchronous and asynchronous timing must be met.
2. This is the shortest pulse that is guaranteed to be recognized.
3. Only PTC2 has high drive capability and load is 75 pF, other pins load (low drive) is 25 pF.

## 5.4 Thermal specifications

### 5.4.1 Thermal operating requirements

**Table 11. Thermal operating requirements**

| Symbol | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $T_J$ | Die junction temperature | –40 | 105 | °C |
| $T_A$ | Ambient temperature | –40 | 85 | °C |

### 5.4.2 Thermal attributes

| Board type | Symbol | Description | 100 LQFP | 44 LGA | Unit | Notes |
|---|---|---|---|---|---|---|
| Single-layer (1s) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 63 | 95 | °C/W | 1 |
| Four-layer (2s2p) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 50 | 50 | °C/W | 1 |
| Single-layer (1s) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./ min. air speed) | 53 | 79 | °C/W | 1 |
| Four-layer (2s2p) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./ min. air speed) | 44 | 45 | °C/W | 1 |
| — | $R_{\theta JB}$ | Thermal resistance, junction to board | 36 | 35 | °C/W | 2 |
| — | $R_{\theta JC}$ | Thermal resistance, junction to case | 18 | 28 | °C/W | 3 |
| — | $\Psi_{JT}$ | Thermal characterization parameter, junction to package top outside center (natural convection) | 3 | 4 | °C/W | 4 |

1. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*, or EIA/JEDEC Standard JESD51-6, *Integrated Circuit Thermal Test Method Environmental Conditions—Forced Convection (Moving Air)*.
2. Determined according to JEDEC Standard JESD51-8, *Integrated Circuit Thermal Test Method Environmental Conditions—Junction-to-Board*.
3. Determined according to Method 1012.1 of MIL-STD 883, *Test Method Standard, Microcircuits*, with the cold plate temperature used for the case temperature. The value includes the thermal resistance of the interface material between the top of the package and the cold plate.
4. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*.

# 6 Peripheral operating requirements and behaviors

## 6.1 Core modules

### 6.1.1 Single Wire Debug (SWD)

**Table 12. SWD switching characteristics at 2.7 V (2.7-3.6 V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| SWD CLK | Frequency of SWD operation | 20 | MHz | 1 |
| Inputs, tSUI | Data setup time | 5 | ns | 1 |
| inputs,tHI | Data hold time | 0 | ns | 1 |
| after clock edge, tDVO | Data valid Time | 32 | ns | 1 |
| tHO | Data Valid Hold | 0 | ns | 1 |

1. Input transition assumed =1 ns. Output transition assumed = 50 pf.

**Table 13. Switching characteristics at 1.7 V (1.7-3.6 V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| SWD CLK | Frequency of SWD operation | 18 | MHz | |
| Inputs, tSUI | Data setup time | 4.7 | ns | |
| inputs,tHI | Data hold time | 0 | ns | |
| after clock edge, tDVO | Data valid Time | 49.4 | ns | 2 |
| tHO | Data Valid Hold | 0 | ns | |

1. Frequency of SWD clock (18 Mhz) is applicable only in case the input setup time of the device outside is not more than 6.15 ns, else the frequency of SWD clock would need to be lowered.

### 6.1.2 Analog Front End (AFE)

**AFE switching characteristics at (2.7 V-3.6 V)**

**Case1:** Clock is coming In and Data is also coming In (XBAR ports timed with respect to the XBAR ports timed with respect to AFE clock defined at pad ptb[7] and pte[3])

**Table 14. AFE switching characteristics (2.7 V-3.6 V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| AFE CLK | Frequency of operation | 10 | MHz | 1 |
| Inputs, tSUI | Data setup time | 5 | ns | 1 |
| inputs,tHI | Data hold time | 0 | ns | 1 |

1. Input Transition: 1ns. Output Load: 50 pf.

**Case 2:** Clock is going Out and Data is coming In (XBAR ports timed with respect to generated clock defined at the XBAR out ports)

**Table 15. AFE switching characteristics (2.7V-3.6V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| AFE CLK | Frequency of operation | 6.2 | MHz | |
| Inputs, tSUI | Data setup time | 36 | ns | |
| inputs,tHI | Data hold time | 0 | ns | |

### AFE switching characteristics at (1.7 V-3.6 V)

**Case1:** Clock is coming In and Data is also coming In ( XBAR ports timed with respect to AFE clock defined at pad ptb[7] and pte[3])

**Table 16. AFE switching characteristics (1.7 V-3.6 V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| AFE CLK | Frequency of operation | 10 | MHz | |
| Inputs, tSUI | Data setup time | 5.1 | ns | |
| inputs,tHI | Data hold time | 0 | ns | |

Case 2: Clock is going Out and Data is coming In ( XBAR ports timed with respect to generated clock defined at XBAR out ports)

**Table 17. AFE switching characteristics (1.7 V-3.6 V)**

| Symbol | Description | Value | Unit | Notes |
|---|---|---|---|---|
| AFE CLK | Frequency of operation | 6.2 | MHz | |
| Inputs, tSUI | Data setup time | 54 | ns | |
| inputs,tHI | Data hold time | 0 | ns | |

## 6.2 Clock modules

### 6.2.1 MCG specifications

**Table 18. MCG specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{ints_ft}$ | Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C | — | 32.768 | — | kHz | |

*Table continues on the next page...*

## Table 18. MCG specifications (continued)

| Symbol | Description | | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $\Delta f_{ints_t}$ | Total deviation of internal reference frequency (slow clock) over voltage and temperature | | — | ± 4 | ± 15 | % | |
| $f_{ints_t}$ | Internal reference frequency (slow clock) — user trimmed | | 31.25 | — | 33.4234 | kHz | |
| $\Delta_{fdco_res_t}$ | Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM | | — | ± 0.3 | ± 0.6 | $\%f_{dco}$ | 1 |
| $\Delta f_{dco_t}$ | Total deviation of trimmed average DCO output frequency over voltage and temperature | | — | | | $\%f_{dco}$ | 1 |
| $\Delta f_{dco_t}$ | Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C | | — | | | $\%f_{dco}$ | 1 |
| $f_{intf_ft}$ | Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C | | | | 4 | MHz | |
| $\Delta f_{intf_t}$ | Total deviation of internal reference frequency (fast clock) over voltage and temperature | | — | ± 10 | ± 15 | % | |
| $f_{intf_t}$ | Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C | | 3 | — | 5 | MHz | |
| $f_{loc_low}$ | Loss of external clock minimum frequency — RANGE = 00 | | (3/5) x $f_{ints_t}$ | — | — | kHz | |
| $f_{loc_high}$ | Loss of external clock minimum frequency — RANGE = 01, 10, or 11 | | (16/5) x $f_{ints_t}$ | — | — | kHz | |
| FLL | | | | | | | |
| $f_{dco}$ | DCO output frequency range | Low-range (DRS=00) $640 \times f_{ints_t}$ | 20 | 20.97 | 22 | MHz | 2, 3 |
| | | Mid-range (DRS=01) $1280 \times f_{ints_t}$ | 40 | 41.94 | 45 | MHz | |
| | | Mid-high range (DRS=10) $1920 \times f_{ints_t}$ | 60 | 62.91 | 67 | MHz | |
| | | High-range (DRS=11) $2560 \times f_{ints_t}$ | 80 | 83.89 | 90 | MHz | |
| $f_{dco_t_DMX32}$ | DCO output frequency | Low-range (DRS=00) $732 \times f_{ints_t}$ | — | 23.99 | — | MHz | 4, 5, 6 |
| | | Mid-range (DRS=01) $1464 \times f_{ints_t}$ | — | 47.97 | — | MHz | |
| | | Mid-high range (DRS=10) $2197 \times f_{ints_t}$ | — | 71.99 | — | MHz | |
| | | High-range (DRS=11) $2929 \times f_{ints_t}$ | — | 95.98 | — | MHz | |
| $J_{cyc_fll}$ | FLL period jitter | | — | 70 | 140 | ps | 7 |
| $t_{fll_acquire}$ | FLL target frequency acquisition time | | — | — | 1 | ms | 8 |
| PLL | | | | | | | |

*Table continues on the next page...*

**Table 18. MCG specifications (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{vco}$ | VCO operating frequency | 11.71875 | 12.288 | 14.6484375 | MHz | |
| $I_{pll}$ | PLL operating current<br>• IO 3.3 V current<br>• Max core voltage current | — | 300<br>100 | — | μA | 9 |
| $f_{pll_ref}$ | PLL reference frequency range | 31.25 | 32.768 | 39.0625 | kHz | |
| $J_{cyc_pll}$ | PLL period jitter (RMS)<br>• $f_{vco}$ = 12 MHz | | | 700 | ps | 10 |
| $D_{lock}$ | Lock entry frequency tolerance | ± 1.49 | — | ± 2.98 | % | 11 |
| $D_{unl}$ | Lock exit frequency tolerance | ± 4.47 | — | ± 5.97 | % | |
| $t_{pll_lock}$ | Lock detector detection time | — | — | $150 \times 10^{-6} + 1075(1/f_{pll_ref})$ | s | 12 |

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
3. Chip max freq is 50 MHz, so Mid-range with DRS = 10 and High-range of DCO cannot be used and should not be configured.
4. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
5. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
6. Chip max freq is 50 MHz, so Mid-range with DRS = 10 and High-range of DCO cannot be used and should not be configured.
7. This specification is based on standard deviation (RMS) of period or frequency.
8. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.
9. Excludes any oscillator currents that are also consuming power while PLL is in operation.
10. This specification was obtained using a Freescale developed PCB. PLL jitter is dependent on the noise characteristics of each PCB and results will vary.
11. Will be updated later
12. This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

## 6.2.2 Oscillator electrical specifications

### 6.2.2.1 Oscillator DC electrical specifications

**Table 19. Oscillator DC electrical specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $V_{DD}$ | Supply voltage | 1.71 | — | 3.6 | V | |

*Table continues on the next page...*

## Table 19. Oscillator DC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $I_{DDOSC}$ | Supply current — low-power mode (HGO=0) | | | | | 1 |
| | • 32 kHz | — | 500 | — | nA | |
| | • 1 MHz | — | 200 | — | μA | |
| | • 4 MHz | — | 200 | — | μA | |
| | • 8 MHz (RANGE=01) | — | 300 | — | μA | |
| | • 16 MHz | — | 950 | — | μA | |
| | • 24 MHz | — | 1.2 | — | mA | |
| | • 32 MHz | — | 1.5 | — | mA | |
| $I_{DDOSC}$ | Supply current — high-gain mode (HGO=1) | | | | | 1 |
| | • 32 kHz | — | 25 | — | μA | |
| | • 1 MHz | — | 300 | — | μA | |
| | • 4 MHz | — | 400 | — | μA | |
| | • 8 MHz (RANGE=01) | — | 500 | — | μA | |
| | • 16 MHz | — | 2.5 | — | mA | |
| | • 24 MHz | — | 3 | — | mA | |
| | • 32 MHz | — | 4 | — | mA | |
| $C_x$ | EXTAL load capacitance | — | — | — | | 2, 3 |
| $C_y$ | XTAL load capacitance | — | — | — | | 2, 3 |
| | Capacitance of EXTAL<br>• Die level (100 LQFP)<br>• Package level (100 LQFP) | 247<br>0.495 | — | — | ff<br>pF | |
| | Capacitance of XTAL<br>• Die level (100 LQFP)<br>• Package level (100 LQFP) | 265<br>0.495 | — | — | ff<br>pF | |
| $R_F$ | Feedback resistor — low-frequency, low-power mode (HGO=0) | — | — | — | MΩ | 2, 4 |
| | Feedback resistor — low-frequency, high-gain mode (HGO=1) | — | 10 | — | MΩ | |
| | Feedback resistor — high-frequency, low-power mode (HGO=0) | — | — | — | MΩ | |
| | Feedback resistor — high-frequency, high-gain mode (HGO=1) | — | 1 | — | MΩ | |

*Table continues on the next page...*

**Table 19. Oscillator DC electrical specifications (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $R_S$ | Series resistor — low-frequency, low-power mode (HGO=0) | — | — | — | kΩ | |
| | Series resistor — low-frequency, high-gain mode (HGO=1) | — | 200 | — | kΩ | |
| | Series resistor — high-frequency, low-power mode (HGO=0) | — | — | — | kΩ | |
| | Series resistor — high-frequency, high-gain mode (HGO=1) | | | | | |
| | • 1 MHz resonator | — | 6.6 | — | kΩ | |
| | • 2 MHz resonator | — | 3.3 | — | kΩ | |
| | • 4 MHz resonator | — | 0 | — | kΩ | |
| | • 8 MHz resonator | — | 0 | — | kΩ | |
| | • 16 MHz resonator | — | 0 | — | kΩ | |
| | • 20 MHz resonator | — | 0 | — | kΩ | |
| | • 32 MHz resonator | — | 0 | — | kΩ | |
| $V_{pp}$[5] | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1) | — | $V_{DD}$ | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1) | — | $V_{DD}$ | — | V | |

1. $V_{DD}$=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. $C_x$ and $C_y$ can be provided by using either integrated capacitors or external components.
4. When low-power mode is selected, $R_F$ is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other device.

## 6.2.2.2 Oscillator frequency specifications

**Table 20. Oscillator frequency specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{osc_lo}$ | Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00) | 32 | — | 40 | kHz | |
| $f_{osc_hi_1}$ | Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01) | 1 | — | 8 | MHz | |

*Table continues on the next page...*

**Table 20. Oscillator frequency specifications (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{osc_hi_2}$ | Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x) | 8 | — | 32 | MHz | |
| $f_{ec_extal}$ | Input clock frequency (external clock mode) | — | — | 48 | MHz | 1, 2 |
| $t_{dc_extal}$ | Input clock duty cycle (external clock mode) | 40 | 50 | 60 | % | |
| $t_{cst}$ | Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0) | — | | — | ms | 3, 4 |
| | Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1) | — | | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0) | — | 0.6 | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1) | — | 1 | — | ms | |

1. Other frequency limits may apply when external clock is being used as a reference for the FLL or PLL.
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

## 6.2.3 32 kHz oscillator electrical characteristics

### 6.2.3.1 32 kHz oscillator DC electrical specifications

**Table 21. 32kHz oscillator DC electrical specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|
| $V_{BAT}$ | Supply voltage | 1.71 | — | 3.6 | V |
| $R_F$ | Internal feedback resistor | — | 100 | — | MΩ |
| $C_{para}$ | Parasitical capacitance of EXTAL32 and XTAL32 | — | 5 | 7 | pF |
| $V_{pp}$[1] | Peak-to-peak amplitude of oscillation | — | 0.6 | — | V |

1. When a crystal is being used with the 32 kHz oscillator, the EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.

### 6.2.3.2 32 kHz oscillator frequency specifications

**Table 22. 32 kHz oscillator frequency specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{osc_lo}$ | Oscillator crystal | — | 32.768 | — | kHz | |

*Table continues on the next page...*

**Table 22. 32 kHz oscillator frequency specifications (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $t_{start}$ | Crystal start-up time | — | 1000 | — | ms | 1 |
| $v_{ec_extal32}$ | Externally provided input clock amplitude | 700 | — | $V_{BAT}$ | mV | 2 , 3 |

1. Proper PC board layout procedures must be followed to achieve specifications.
2. This specification is for an externally supplied clock driven to EXTAL32 and does not apply to any other clock input. The oscillator remains enabled and XTAL32 must be left unconnected.
3. The parameter specified is a peak-to-peak value and $V_{IH}$ and $V_{IL}$ specifications do not apply. The voltage of the applied clock must be within the range of $V_{SS}$ to $V_{BAT}$.

**NOTE**

The 32 kHz oscillator works in low power mode by default and cannot be moved into high power/gain mode.

## 6.3 Memories and memory interfaces

### 6.3.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

#### 6.3.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

**Table 23. NVM program/erase timing specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $t_{hvpgm4}$ | Longword Program high-voltage time | — | 7.5 | 18 | μs | |
| $t_{hversscr}$ | Sector Erase high-voltage time | — | 13 | 113 | ms | 1 |
| $t_{hversall}$ | Erase All high-voltage time | — | 52 | 452 | ms | 1 |

1. Maximum time based on expectations at cycling end-of-life.

#### 6.3.1.2 Flash timing specifications — commands

**Table 24. Flash command timing specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $t_{rd1sec1k}$ | Read 1s Section execution time (flash sector) | — | — | 60 | μs | 1 |
| $t_{pgmchk}$ | Program Check execution time | — | — | 45 | μs | 1 |
| $t_{rdrsrc}$ | Read Resource execution time | — | — | 30 | μs | 1 |

*Table continues on the next page...*

**Table 24. Flash command timing specifications (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $t_{pgm4}$ | Program Longword execution time | — | 65 | 145 | μs | |
| $t_{ersscr}$ | Erase Flash Sector execution time | — | 14 | 114 | ms | 2 |
| $t_{rd1all}$ | Read 1s All Blocks execution time | — | — | 1.8 | ms | |
| $t_{rdonce}$ | Read Once execution time | — | — | 25 | μs | 1 |
| $t_{pgmonce}$ | Program Once execution time | — | 65 | — | μs | |
| $t_{ersall}$ | Erase All Blocks execution time | — | 88 | 650 | ms | 2 |
| $t_{vfykey}$ | Verify Backdoor Access Key execution time | — | — | 30 | μs | 1 |

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

### 6.3.1.3 Flash high voltage current behaviors

**Table 25. Flash high voltage current behaviors**

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|
| $I_{DD_PGM}$ | Average current adder during high voltage flash programming operation | — | 2.5 | 6.0 | mA |
| $I_{DD_ERS}$ | Average current adder during high voltage flash erase operation | — | 1.5 | 4.0 | mA |

### 6.3.1.4 Reliability specifications

**Table 26. NVM reliability specifications**

| Symbol | Description | Min. | Typ.[1] | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| Program Flash | | | | | | |
| $t_{nvmretp10k}$ | Data retention after up to 10 K cycles | 5 | 50 | — | years | |
| $t_{nvmretp1k}$ | Data retention after up to 1 K cycles | 20 | 100 | — | years | |
| $n_{nvmcycp}$ | Cycling endurance | 10 K | 50 K | — | cycles | 2 |

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25 °C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at -40 °C ≤ $T_j$ ≤ 125 °C.

## 6.4 Analog

### 6.4.1 ADC electrical specifications

All ADC channels meet the 12-bit single-ended accuracy specifications.

### 6.4.1.1 16-bit ADC operating conditions

**Table 27. 16-bit ADC operating conditions**

| Symbol | Description | Conditions | Min. | Typ.[1] | Max. | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $V_{DDA}$ | Supply voltage | Absolute | 1.71 | — | 3.6 | V | |
| $\Delta V_{DDA}$ | Supply voltage | Delta to $V_{DD}$ ($V_{DD} – V_{DDA}$) | -100 | 0 | +100 | mV | 2 |
| $\Delta V_{SSA}$ | Ground voltage | Delta to $V_{SS}$ ($V_{SS} – V_{SSA}$) | -100 | 0 | +100 | mV | 2 |
| $V_{REFH}$ | ADC reference voltage high | | 1.13 | $V_{DDA}$ | $V_{DDA}$ | V | |
| $V_{REFL}$ | ADC reference voltage low | | $V_{SSA}$ | $V_{SSA}$ | $V_{SSA}$ | V | |
| $V_{ADIN}$ | Input voltage | | $V_{REFL}$ | — | $V_{REFH}$ | V | |
| $C_{ADIN}$ | Input capacitance | • 16-bit mode<br>• 8-bit / 10-bit / 12-bit modes | —<br>— | 8<br>4 | 10<br>5 | pF | |
| $R_{ADIN}$ | Input series resistance | | — | 2 | 5 | kΩ | |
| $R_{AS}$ | Analog source resistance (external) | 12-bit modes<br>$f_{ADCK}$ < 4 MHz | — | — | 5 | kΩ | 3 |
| $f_{ADCK}$ | ADC conversion clock frequency | ≤ 12-bit mode | 1.0 | — | 18.0 | MHz | 4 |
| $f_{ADCK}$ | ADC conversion clock frequency | 16-bit mode | 2.0 | — | 12.0 | MHz | 4 |
| $C_{rate}$ | ADC conversion rate | ≤ 12-bit modes<br>No ADC hardware averaging<br>Continuous conversions enabled, subsequent conversion time | 20.000 | — | 818.330 | Ksps | 5 |
| $C_{rate}$ | ADC conversion rate | 16-bit mode<br>No ADC hardware averaging<br>Continuous conversions enabled, subsequent conversion time | 37.037 | — | 461.467 | Ksps | 5 |

1. Typical values assume $V_{DDA}$ = 3.0 V, Temp = 25 °C, $f_{ADCK}$ = 1.0 MHz, unless otherwise stated. Typical values are for reference only, and are not tested in production.
2. DC potential difference.
3. This resistance is external to MCU. To achieve the best results, the analog source resistance must be kept as low as possible. The results in this data sheet were derived from a system that had < 8 Ω analog source resistance. The $R_{AS}/C_{AS}$ time constant should be kept to < 1 ns.
4. To use the maximum ADC conversion clock frequency, CFG2[ADHSC] must be set and CFG1[ADLPC] must be clear.
5. For guidelines and examples of conversion rate calculation, download the ADC calculator tool.

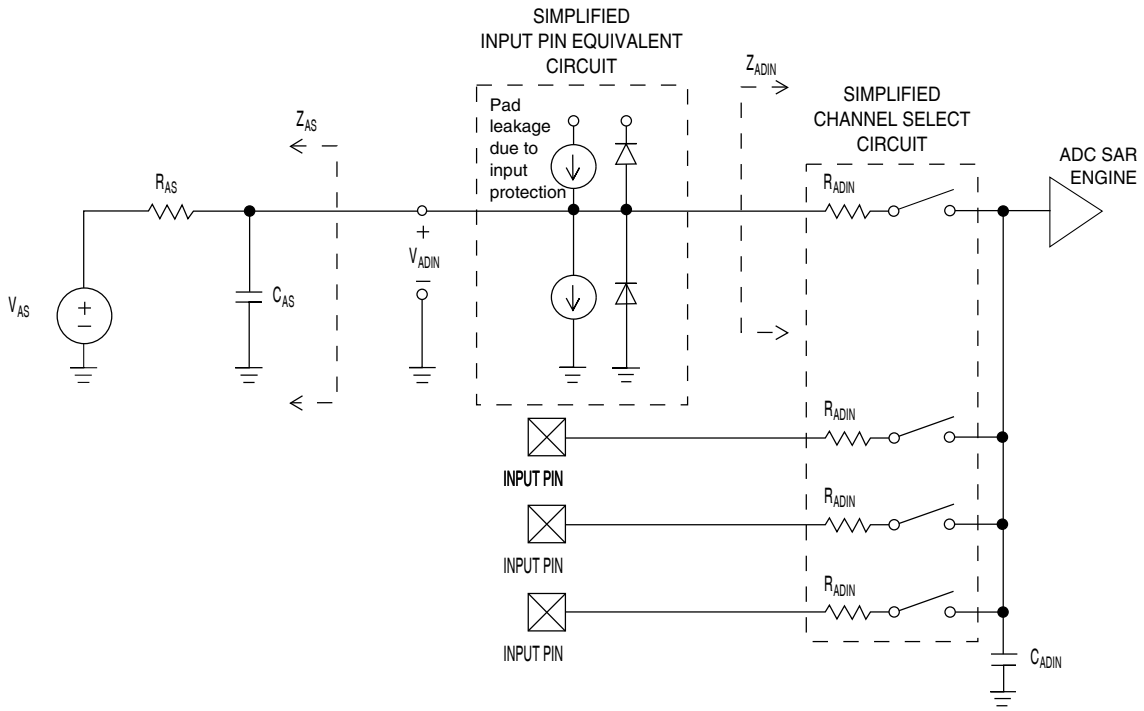



**Figure 2. ADC input impedance equivalency diagram**

## 6.4.1.2 16-bit ADC electrical characteristics

**Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$)**

| Symbol | Description | Conditions[1]. | Min. | Typ.[2] | Max. | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $I_{DDA_ADC}$ | Supply current | | 0.215 | — | 1.7 | mA | 3 |
| $f_{ADACK}$ | ADC asynchronous clock source | • ADLPC = 1, ADHSC = 0<br>• ADLPC = 1, ADHSC = 1<br>• ADLPC = 0, ADHSC = 0<br>• ADLPC = 0, ADHSC = 1 | 1.2<br>2.4<br>3.0<br>4.4 | 2.4<br>4.0<br>5.2<br>6.2 | 3.9<br>6.1<br>7.3<br>9.5 | MHz<br>MHz<br>MHz<br>MHz | $t_{ADACK} = 1/f_{ADACK}$ |
| | Sample Time | See Reference Manual chapter for sample times | | | | | |
| TUE | Total unadjusted error | • 12-bit modes<br>• <12-bit modes | —<br>— | ±4<br>±1.4 | ±6.8<br>±2.1 | LSB[4] | 5 |
| DNL | Differential non-linearity | • 12-bit modes<br>• <12-bit modes | —<br>— | ±0.7<br>±0.2 | –1.1 to +1.9<br>–0.3 to 0.5 | LSB[4] | 5 |
| INL | Integral non-linearity | • 12-bit modes<br>• <12-bit modes | —<br>— | ±1.0<br>±0.5 | –2.7 to +1.9<br>–0.7 to +0.5 | LSB[4] | 5 |

*Table continues on the next page...*

## Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

| Symbol | Description | Conditions[1]. | Min. | Typ.[2] | Max. | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $E_{FS}$ | Full-scale error | • 12-bit modes<br>• <12-bit modes | —<br>— | –4<br>–1.4 | –5.4<br>–1.8 | LSB[4] | $V_{ADIN} = V_{DDA}$[5] |
| $E_Q$ | Quantization error | • 16-bit modes<br>• 12-bit modes | —<br>— | –1 to 0<br>— | —<br>±0.5 | LSB[4] | |
| ENOB | Effective number of bits | 16-bit single-ended mode<br>• Avg = 32<br>• Avg = 4 | <br>12.8<br>11.9<br><br>12.2<br>11.4 | <br>14.5<br>13.8<br><br>13.9<br>13.1 | <br>—<br>—<br><br>—<br>— | <br>bits<br>bits<br><br>bits<br>bits | 6 |
| SINAD | Signal-to-noise plus distortion | See ENOB | 6.02 × ENOB + 1.76 | | | dB | |
| THD | Total harmonic distortion | 16-bit single-ended mode<br>• Avg = 32 | <br>—<br>— | <br>-94<br>-85 | <br>—<br>— | <br>dB<br>dB | 7 |
| SFDR | Spurious free dynamic range | 16-bit single-ended mode<br>• Avg = 32 | <br>82<br>78 | <br>95<br>90 | <br>—<br>— | <br>dB<br>dB | 7 |
| $E_{IL}$ | Input leakage error | | $I_{In} \times R_{AS}$ | | | mV | $I_{In}$ = leakage current<br>(refer to the MCU's voltage and current operating ratings) |
| | Temp sensor slope | Across the full temperature range of the device | 1.55 | 1.62 | 1.69 | mV/°C | 8 |
| $V_{TEMP25}$ | Temp sensor voltage | 25 °C | 706 | 716 | 726 | mV | 8 |

1. All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$
2. Typical values assume $V_{DDA}$ = 3.0 V, Temp = 25 °C, $f_{ADCK}$ = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
7. Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.

8. ADC conversion clock < 3 MHz

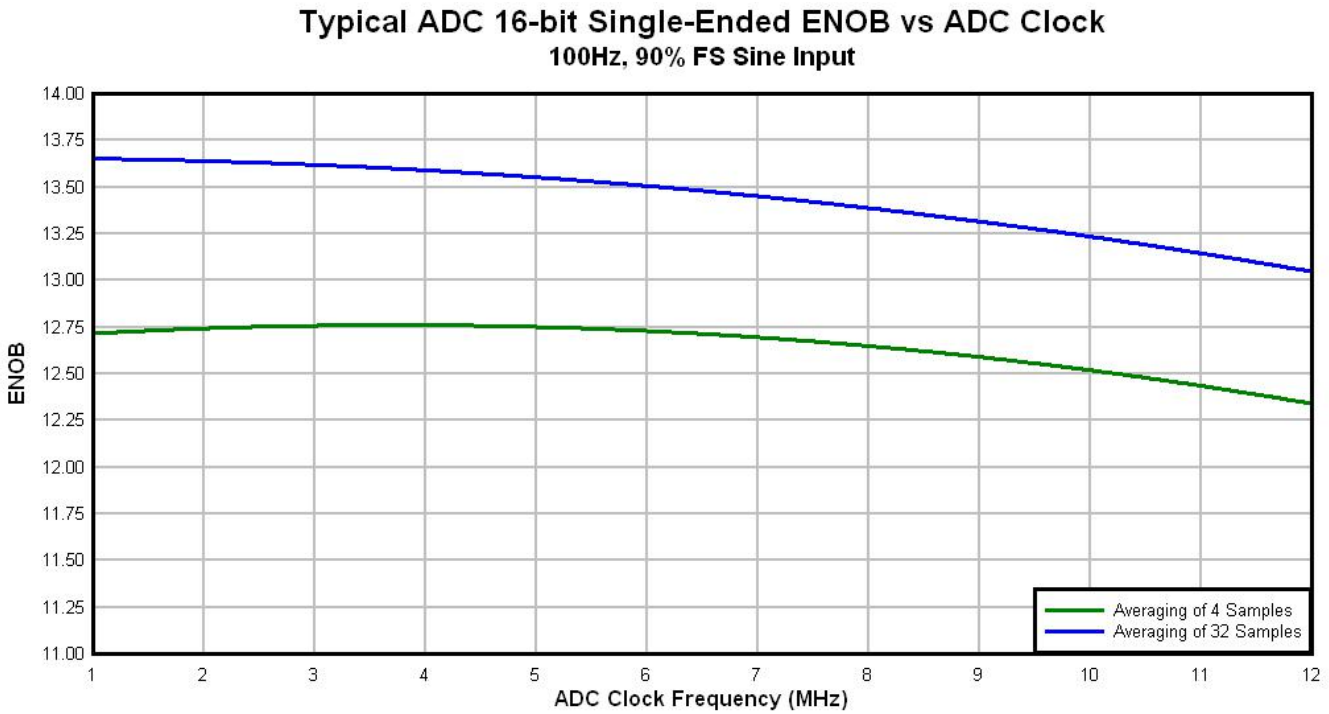



**Figure 3. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode**

## 6.4.2 CMP and 6-bit DAC electrical specifications

**Table 29. Comparator and 6-bit DAC electrical specifications**

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|
| $V_{DD}$ | Supply voltage | 1.71 | — | 3.6 | V |
| $I_{DDHS}$ | Supply current, High-speed mode (EN=1, PMODE=1) | — | — | 200 | μA |
| $I_{DDLS}$ | Supply current, low-speed mode (EN=1, PMODE=0) | — | — | 20 | μA |
| $V_{AIN}$ | Analog input voltage | $V_{SS}$ – 0.3 | — | $V_{DD}$ | V |
| $V_{AIO}$ | Analog input offset voltage | — | — | 20 | mV |
| $V_H$ | Analog comparator hysteresis[1] | | | | |
| | • CR0[HYSTCTR] = 00 | — | 5 | — | mV |
| | • CR0[HYSTCTR] = 01 | — | 10 | — | mV |
| | • CR0[HYSTCTR] = 10 | — | 20 | — | mV |
| | • CR0[HYSTCTR] = 11 | — | 30 | — | mV |
| $V_{CMPOh}$ | Output high | $V_{DD}$ – 0.5 | — | — | V |
| $V_{CMPOl}$ | Output low | — | — | 0.5 | V |
| $t_{DHS}$ | Propagation delay, high-speed mode (EN=1, PMODE=1) | 20 | 50 | 200 | ns |

*Table continues on the next page...*

## Table 29. Comparator and 6-bit DAC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|
| $t_{DLS}$ | Propagation delay, low-speed mode (EN=1, PMODE=0) | 80 | 250 | 600 | ns |
| | Analog comparator initialization delay[2] | — | — | 40 | μs |
| $I_{DAC6b}$ | 6-bit DAC current adder (enabled) | — | 7 | — | μA |
| INL | 6-bit DAC integral non-linearity | –0.5 | — | 0.5 | LSB[3] |
| DNL | 6-bit DAC differential non-linearity | –0.3 | — | 0.3 | LSB |

1. Typical hysteresis is measured with input voltage range limited to 0.6 to $V_{DD}$–0.6 V.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]) and the comparator output settling to a stable level.
3. 1 LSB = $V_{reference}/64$

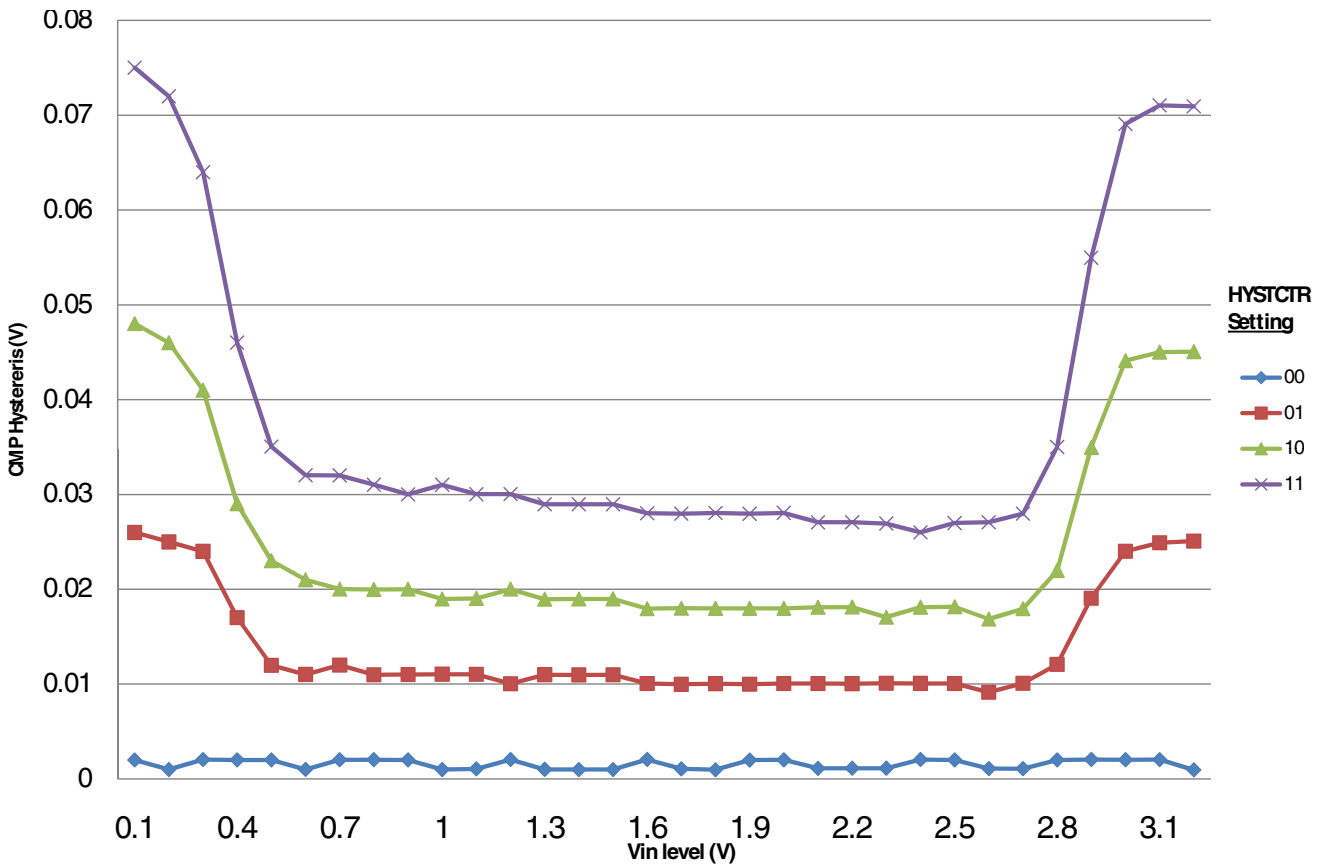



**Figure 4. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)**

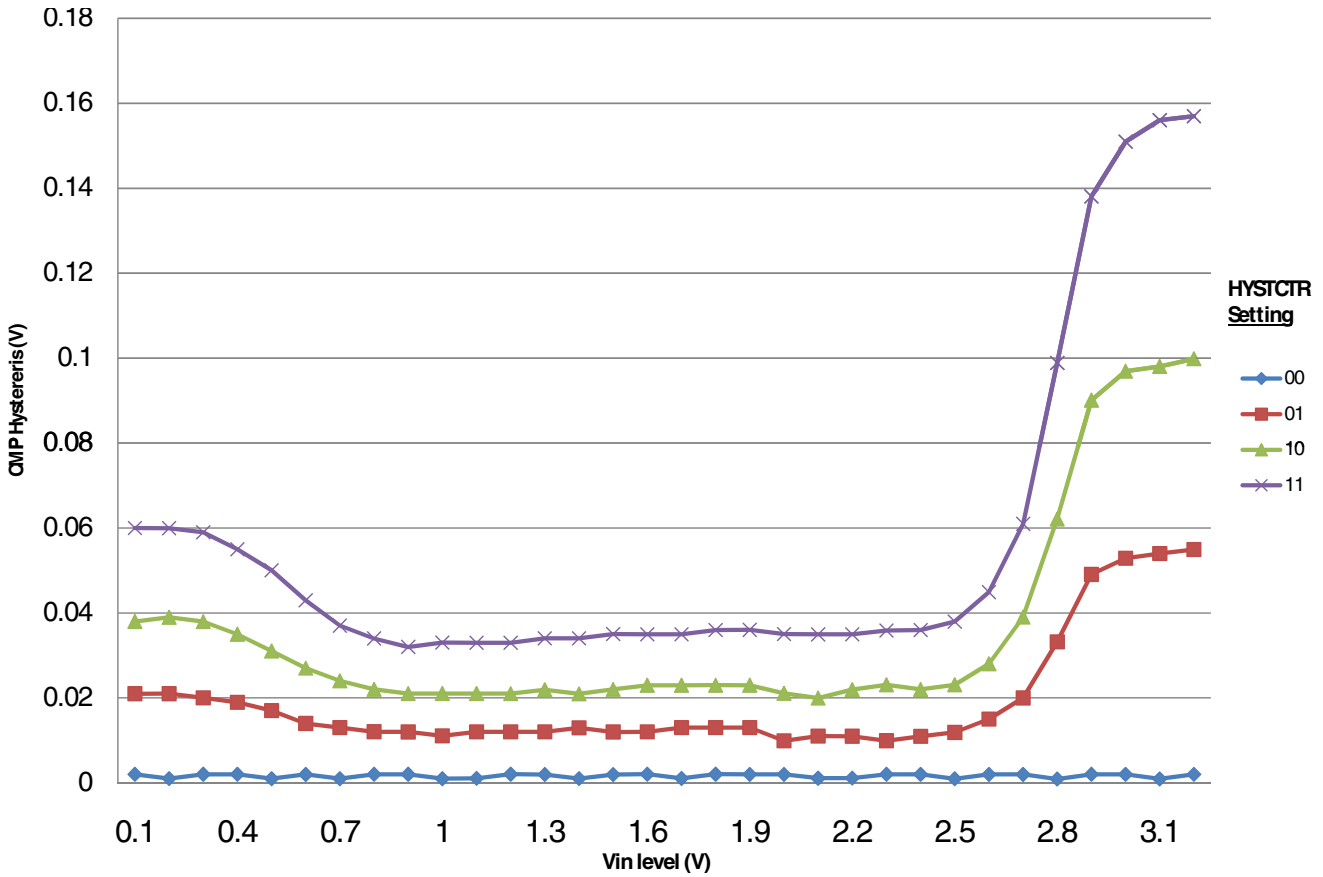



**Figure 5. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)**

## 6.4.3 Voltage reference electrical specifications

**Table 30. 1.2 VREF full-range operating requirements**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $V_{DDA}$ | Supply voltage | 1.71[1] | 3.6 | V | |
| $T_A$ | Temperature | –40 | 85 | °C | |
| $C_L$ | Output load capacitance | 100 | | nF | 2, 3 |

1. AFE is enabled.
2. $C_L$ must be connected between VREFH and VREFL.
3. The load capacitance should not exceed +/-25% of the nominal specified $C_L$ value over the operating temperature range of the device.

**Table 31. VREF full-range operating behaviors**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| VREFH | Voltage reference output with factory trim at nominal $V_{DDA}$ and temperature = 25 °C | 1.1915 | 1.2 | 1.2027 | V | |
| VREFH | Voltage reference output with — factory trim | 1.1584 | — | 1.2376 | V | |

*Table continues on the next page...*

**Table 31. VREF full-range operating behaviors (continued)**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| VREFH | Voltage reference output — user trim | 1.178 | — | 1.202 | V | |
| VREFL | Voltage reference output | 0.38 | 0.4 | 0.42 | V | |
| $V_{step}$ | Voltage reference trim step | — | 0.5 | — | mV | |
| $V_{tdrift}$ | Temperature drift (Vmax - Vmin across the full temperature range) | — | 5 | — | mV | 1 |
| Ac | Aging coefficient | — | — | 400 | uV/yr | |
| $I_{bg}$ | Bandgap only current | — | — | 80 | μA | 2 |
| $I_{lp}$ | Low-power buffer current | — | — | 0.19 | μA | 2 |
| $I_{hp}$ | High-power buffer current | — | — | 0.5 | mA | 2 |
| $I_{LOAD}$ | VREF buffer current | — | — | 1 | mA | 3 |
| $\Delta V_{LOAD}$ | Load regulation<br>• current = + 1.0 mA<br>• current = - 1.0 mA | —<br>— | <br>2<br>5 | <br>— | mV | 2, 4 |
| $T_{stup}$ | Buffer startup time | — | — | 20 | ms | |
| $V_{vdrift}$ | Voltage drift (Vmax -Vmin across the full voltage range) | — | 0.5 | — | mV | 2 |

1. For temp range -40 °C to 105 °C, this value is 15 mV
2. See the chip's Reference Manual for the appropriate settings of VREF Status and Control register.
3. See the chip's Reference Manual for the appropriate settings of SIM Miscellaneous Control Register.
4. Load regulation voltage is the difference between VREFH voltage with no load vs. voltage with defined load.

**Table 32. VREF limited-range operating requirements**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| $T_A$ | Temperature | 0 | 50 | °C | |

**Table 33. VREF limited-range operating behaviours**

| Symbol | Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|---|
| VREFH | Voltage reference output with factory trim | 1.173 | 1.225 | V | |
| VREFL | Voltage reference output | 0.38 | 0.42 | V | |

## 6.4.4 AFE electrical specifications

### 6.4.4.1 ΣΔ ADC + PGA specifications

**Table 34. ΣΔ ADC + PGA specifications**

| Symbol | Description | Conditions | Min | Typ[1] | Max | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $f_{Nyq}$ | Input bandwidth | Normal Mode | 1.5 | 1.5 | 1.5 | kHz | |
| | | Low-Power Mode | 1.5 | 1.5 | 1.5 | | |
| $V_{CM}$ | Input Common Mode Reference | | 0 | | 0.8 | V | |
| $VIN_{diff}$ | Differential input range | Gain = 1 (PGA ON/OFF)[2] | | +/- 500 | | mV | |
| | | Gain = 2 | | +/- 250 | | mV | |
| | | Gain = 4 | | +/- 125 | | mV | |
| | | Gain = 8 | | +/- 62 | | mV | |
| | | Gain = 16 | | +/- 31 | | mV | |
| | | Gain = 32 | | +/- 15 | | mV | |
| SNR | Signal to Noise Ratio | Normal Mode | | | | dB | |
| | | • $f_{IN}$=50Hz; gain=01, common mode=0V, $V_{pp}$=1000mV (full range diff.) | 90 | 92 | | | |
| | | • $f_{IN}$=50Hz; gain=02, common mode=0V, $V_{pp}$= 500mV (differential ended ) | 88 | 90 | | | |
| | | • $f_{IN}$=50Hz; gain=04, common mode=0V, $V_{pp}$= 250mV (differential ended ) | 82 | 86 | | | |
| | | • $f_{IN}$=50Hz; gain=08, common mode=0V, $V_{pp}$= 125mV (differential ended ) | 76 | 82 | | | |
| | | • $f_{IN}$=50Hz; gain=16, common mode=0V, $V_{pp}$= 62mV (differential ended ) | 70 | 78 | | | |
| | | • $f_{IN}$=50Hz; gain=32, common mode=0V, $V_{pp}$= 31mV (differential ended ) | 64 | 74 | | | |
| | | Low-Power Mode | | | | dB | |
| | | • $f_{IN}$=50Hz; gain=01, common mode=0V, $V_{pp}$=1000mV (full range diff.) | 82 | 82 | | | |
| | | • $f_{IN}$=50Hz; gain=02, common mode=0V, $V_{pp}$= 500mV (differential ended ) | 76 | 78 | | | |
| | | • $f_{IN}$=50Hz; gain=04, common mode=0V, $V_{pp}$= 250mV (differential ended ) | 70 | 74 | | | |
| | | • $f_{IN}$=50Hz; gain=08, common mode=0V, $V_{pp}$= 125mV (differential ended ) | 64 | 70 | | | |
| | | • $f_{IN}$=50Hz; gain=16, common mode=0V, $V_{pp}$= 62mV (differential ended ) | 58 | 66 | | | |
| | | • $f_{IN}$=50Hz; gain=32, common mode=0V, $V_{pp}$= 31mV (differential ended ) | 52 | 62 | | | |

*Table continues on the next page...*

## Table 34. ΣΔ ADC + PGA specifications (continued)

| Symbol | Description | Conditions | Min | Typ[1] | Max | Unit | Notes |
|---|---|---|---|---|---|---|---|
| SINAD | Signal-to-Noise + Distortion Ratio | Normal Mode<br>• $f_{IN}$=50Hz; gain=01, common mode=0V, $V_{pp}$=500mV (differential ended ) | | 78 | | dB | |
| | | Low-Power Mode<br>• $f_{IN}$=50Hz; gain=01, common mode=0V, $V_{pp}$=500mV (differential ended ) | | 74 | | dB | |
| CMMR | Common Mode Rejection Ratio | • $f_{IN}$=50Hz; gain=01, common mode=0V, Vid=100 mV<br>• $f_{IN}$=50Hz; gain=32, common mode=0V, $V_{id}$=100 mV | | 70<br>70 | | dB | |
| $E_{offset}$ | Offset Error | Gain=01, $V_{pp}$=1000 mV (full range diff.) | | | +/- 5 | mV | |
| ΔOffset Temp | Offset Temperature Drift[3] | Gain=01, $V_{pp}$=1000mV (full range diff.) | | | +/- 25 | ppm/°C | |
| $\Delta Gain_{Temp}$ | Gain Temperate Drift - Gain error caused by temperature drifts[4] | • Gain=01, $V_{pp}$=500mV (differential ended )<br>• Gain=32, $V_{pp}$=15mV (differential ended ) | | | +/- 75 | ppm/°C | |
| $PSRR_{AC}$ | AC Power Supply Rejection Ratio | Gain=01, VCC = 3V ± 100mV, $f_{IN}$ = 50 Hz | | 60 | | dB | |
| XT | Crosstalk (with the input of the affected channel grounded) | Gain=01, $V_{id}$ = 500 mV, $f_{IN}$ = 50 Hz | | | -100 | dB | |
| $f_{MCLK}$ | Modulator Clock Frequency Range | Normal Mode<br>Low-Power Mode | 0.03<br>0.03 | | 6.5<br>1.6 | MHz | |
| $I_{DDA_PGA}$ | Current consumption by PGA (each channel) | Normal Mode ($f_{MCLK}$ = 6.144 MHz, OSR= 2048)<br>Low-Power Mode ($f_{MCLK}$ = 0.768MHz, OSR= 256) | | | 2.6<br>0 | mA | 5 |
| $I_{DDA_ADC}$ | Current Consumption by ADC (each chanel) | Normal Mode ($f_{MCLK}$ = 6.144 MHz, OSR= 2048)<br>Low-Power Mode ($f_{MCLK}$ = 0.768MHz, OSR= 256) | | | 1.4<br>0.5 | mA | |

1. Typical values assume VDDA = 3.0 V, Temp = 25°C, $f_{MCLK}$ = 6.144 MHz, OSR = 2048 for Normal mode and $f_{MCLK}$ = 768 kHz, OSR = 256 for Low-Power Mode unless otherwise stated. Typical values are for reference only and are not tested in production.
2. The full-scale input range in single-ended mode is 0.5Vpp
3. Represents combined offset temperature drift of the PGA, SD ADC and Internal 1.2 VREF blocks; Defined by shorting both differential inputs to ground.
4. Represents combined gain temperature drift of the PGA, SD ADC and Internal 1.2 VREF blocks.
5. PGA is disabled in low-power modes.

### 6.4.4.2 ΣΔ ADC Standalone specifications

**Table 35. ΣΔ ADC standalone specifications**

| Symbol | Description | Conditions | Min | Typ[1] | Max | Unit | Notes |
|---|---|---|---|---|---|---|---|
| $f_{Nyq}$ | Input bandwidth | Normal Mode<br>Low-Power Mode | 1.5<br>1.5 | 1.5<br>1.5 | 1.5<br>1.5 | kHz | |
| $V_{CM}$ | Input Common Mode Reference | | 0 | | 0.8 | V | |
| $VIN_{diff}$ | Input range | Differential | | +/- 500 | | mV | |
| | | Single Ended | | +/- 250 | | mV | |
| SNR | Signal to Noise Ratio | Normal Mode<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$= 500mV (differential ended )<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$= 500mV (full range se.)<br>Low-Power Mode<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$=500mV (diff.)<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$=500mV (full range se.) | 88<br>76 | 90<br>78 | | dB | |
| $\Delta Gain_{Temp}$ | Gain Temperate Drift - Gain error caused by temperature drifts [2] | • Gain bypassed Vpp = 500 mV (differential)<br>• PGA bypassed Vpp = 500 mV (differential), VCM = 0 V | | | 55 | ppm/°C | |
| $\Delta Offset_{Temp}$ | Offset Temperate Drift - Offset error caused by temperature drifts [3] | • Gain bypassed Vpp = 500 mV (differential), VCM = 0 V | | | 30 | ppm/°C | |
| SINAD | Signal-to-Noise + Distortion Ratio | Normal Mode<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$= 500mV (diff.)<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$= 500mV (full range se.)<br>Low-Power Mode<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$=500mV (diff.)<br>• $f_{IN}$=50Hz; common mode=0V, $V_{pp}$=500mV (full range se.) | | 80<br>74 | | dB | |
| CMMR | Common Mode Rejection Ratio | • $f_{IN}$=50Hz; common mode=0V, $V_{id}$=100 mV | | 90 | | dB | |
| $PSRR_{AC}$ | AC Power Supply Rejection Ratio | Gain=01, VCC = 3V ± 100mV, $f_{IN}$ = 50 Hz | | 60 | | dB | |
| XT | Crosstalk | Gain=01, $V_{id}$ = 500 mV, $f_{IN}$ = 50 Hz | | | -100 | dB | |
| $f_{MCLK}$ | Modulator Clock Frequency Range | Normal Mode<br>Low-Power Mode | 0.03<br>0.03 | | 6.5<br>1.6 | MHz | |
| $I_{DDA_ADC}$ | Current Consumption by ADC (each channel) | Normal Mode ($f_{MCLK}$ = 6.144 MHz, OSR= 2048)<br>Low-Power Mode ($f_{MCLK}$ = 0.768MHz, OSR= 256) | | | 1.4<br>0.5 | mA | |

1. Typical values assume VDDA = 3.0 V, Temp = 25°C, $f_{MCLK}$ = 6.144 MHz, OSR = 2048 for Normal mode and $f_{MCLK}$ = 768 kHz, OSR = 256 for Low-Power Mode unless otherwise stated. Typical values are for reference only and are not tested in production.
2. Represent combined gain temperature drift of the SD ADC, and Internal 1.2 VREF blocks.
3. Represent combined offset temperature drift of the SD ADC, and Internal 1.2 VREF blocks; Defined by shorting both differential inputs to ground.

#### 6.4.4.3 External modulator interface

The external modulator interface on this device comprises of a Clock signal and 1-bit data signal. Depending on the modulator device being used the interface works as follows:

- Clock supplied to external modulator which drives data on rising edge and the KM device captures it on falling edge or next rising edge.
- Clock and data are supplied by external modulator and KM device can sample it on falling edge or next rising edge.

Depending on control bit in AFE, the sampling edge is changed.

## 6.5 Timers

See General switching specifications.

## 6.6 Communication interfaces

### 6.6.1 I2C switching specifications

See General switching specifications.

### 6.6.2 UART switching specifications

See General switching specifications.

### 6.6.3 SPI switching specifications

The Serial Peripheral Interface (SPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The following table provides some reference values to be met on SoC.

**Table 36. SPI switching characteristics at 2.7 V ( 2.7 - 3.6)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| Frequency of operation ($F_{sys}$) | — | 50 | MHz | 1 |
| SCK frequency<br>• Master<br>• Slave | 2 | 12.5<br>12.5 | MHz<br>Mhz | 3 |
| SCK Duty Cycle | 50% | — | — | |
| Data Setup Time (inputs, tSUI)<br>• Master<br>• Slave | 25<br>3 | | ns | |
| Input Data Hold Time (inputs, tHI)<br>• Master<br>• Slave | 0<br>1 | | ns | |
| Data hold time (outputs, tHO)<br>• Master<br>• Slave | 0<br>0 | | ns | |
| Data Valid Out Time (after SCK edge, tDVO)<br>• Master<br>• Slave | 13<br>28 | | ns | |
| Rise time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Fall time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Rise time output<br>• Master<br>• Slave | 8.9<br>8.9 | | ns | |
| Fall time output<br>• Master<br>• Slave | 7.8<br>7.8 | | ns | |

1. SPI modules will work on core clock.
2. $F_{sys}$/(Max Divider Value from registers)
3. $F_{SYS}$/2 in Master mode and $F_{SYS}$/4 in Slave mode. $F_{SYS}$/4 in Master as well as Slave Modes, where $F_{SYS}$=50Mhz

**NOTE**

The values assumed for input transition and output load are:
Input transition = 1 ns Output load = 50 pF

**Table 37. SPI switching characteristics at 1.7 V ( 1.7 - 3.6)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| Frequency of operation ($F_{sys}$) | — | 50 | MHz | |

*Table continues on the next page...*

**Table 37. SPI switching characteristics at 1.7 V ( 1.7 - 3.6) (continued)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| SCK frequency<br>• Master<br>• Slave | | 9<br>9 | MHz<br>Mhz | |
| SCK Duty Cycle | 50% | — | — | |
| Data Setup Time (inputs, tSUI)<br>• Master<br>• Slave | 42<br>3.5 | | ns | |
| Input Data Hold Time (inputs, tHI)<br>• Master<br>• Slave | 0<br>1 | | ns | |
| Data hold time (outputs, tHO)<br>• Master<br>• Slave | -3<br>0 | | ns | |
| Data Valid Out Time (tDVO)<br>• Master<br>• Slave | 16<br>44 | | ns | 1 |
| Rise time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Fall time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Rise time output<br>• Master<br>• Slave | 14.4<br>14.4 | | ns | |
| Fall time output<br>• Master<br>• Slave | 12.4<br>12.4 | | ns | |

1. SCK frequency of 9 Mhz is applicable only in the case that the input setup time of the device outside is not more than 11.5 ns, else the frequency would need to be lowered.

The following table represents SPI Switching specification in OD cells

**Table 38. SPI switching characteristics at 1.7 V ( 1.7 - 3.6)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| Data Setup Time (inputs, tSUI)<br>• Master<br>• Slave | 51<br>4 | | ns | |
| Input Data Hold Time (inputs, tHI)<br>• Master<br>• Slave | 0<br>1 | | ns | |
| Data hold time (outputs, tHO)<br>• Master<br>• Slave | -15<br>0 | | ns | |
| Data Valid Out Time (tDVO)<br>• Master<br>• Slave | 61<br>93 | | ns | |

*Table continues on the next page...*

**Table 38. SPI switching characteristics at 1.7 V ( 1.7 - 3.6) (continued)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| Rise time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Fall time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Rise time output<br>• Master<br>• Slave | 30.4<br>30.4 | | ns | |
| Fall time output<br>• Master<br>• Slave | 33.5<br>29.0 | | ns | |

**Table 39. SPI switching characteristics at 2.7 V ( 2.7 - 3.6)**

| Description | Min. | Max. | Unit | Notes |
|---|---|---|---|---|
| Data Setup Time (inputs, tSUI)<br>• Master<br>• Slave | 29<br>4 | | ns | |
| Input Data Hold Time (inputs, tHI)<br>• Master<br>• Slave | 0<br>1 | | ns | |
| Data hold time (outputs, tHO)<br>• Master<br>• Slave | 0<br>0 | | ns | |
| Data Valid Out Time (after SCK edge, tDVO)<br>• Master<br>• Slave | 49<br>49 | | ns | |
| Rise time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Fall time input<br>• Master<br>• Slave | 1<br>1 | | ns | |
| Rise time output<br>• Master<br>• Slave | 17.3<br>17.3 | | ns | |
| Fall time output<br>• Master<br>• Slave | 16.6<br>16.0 | | ns | |

## 6.7 Human-Machine Interfaces (HMI)

### 6.7.1 LCD electrical characteristics

**Table 40. LCD electricals**

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---|---|---|---|---|---|---|
| $f_{Frame}$ | LCD frame frequency | 28 | 30 | 58 | Hz | |
| $C_{LCD}$ | LCD charge pump capacitance — nominal value | — | 100 | — | nF | 1 |
| $C_{BYLCD}$ | LCD bypass capacitance — nominal value | — | 100 | — | nF | 1 |
| $C_{Glass}$ | LCD glass capacitance | — | 2000 | 8000 | pF | 2 |
| $V_{IREG}$ | $V_{IREG}$ | | | | | 3 |
| | • HREFSEL=0, RVTRIM=1111 | — | 1.11 | — | V | |
| | • HREFSEL=0, RVTRIM=1000 | — | 1.01 | — | V | |
| | • HREFSEL=0, RVTRIM=0000 | — | 0.91 | — | V | |
| $\Delta_{RTRIM}$ | $V_{IREG}$ TRIM resolution | — | — | 3.0 | % $V_{IREG}$ | |
| $I_{VIREG}$ | $V_{IREG}$ current adder — RVEN = 1 | — | 1 | — | μA | 4 |
| $I_{RBIAS}$ | RBIAS current adder | | | | | |
| | • LADJ = 10 or 11 — High load (LCD glass capacitance ≤ 8000 pF) | — | 15 | — | μA | |
| | • LADJ = 00 or 01 — Low load (LCD glass capacitance ≤ 2000 pF) | — | 3 | — | μA | |
| VLL2 | VLL2 voltage | | | | | |
| | • HREFSEL = 0 | 2.0 – 5% | 2.0 | — | V | |
| VLL3 | VLL3 voltage | 3.0 – 5% | 3.0 | — | V | |

1. The actual value used could vary with tolerance.
2. For highest glass capacitance values, LCD_GCR[LADJ] should be configured as specified in the LCD Controller chapter within the device's reference manual.
3. $V_{IREG}$ maximum should never be externally driven to any level other than $V_{DD}$ - 0.15 V.
4. 2000 pF load LCD, 32 Hz frame frequency.

**NOTE**

KM family devices have a 1/3 bias controller that works with a 1/3 bias LCD glass. To avoid ghosting, the LCD OFF threshold should be greater than VLL1 level. If the LCD glass has an OFF threshold less than VLL1 level, use the internal VREG mode and generate VLL1 internally using RVTRIM option. This can reduce VLL1 level to allow for a lower OFF threshold LCD glass.

# 7 Dimensions

## 7.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to freescale.com and perform a keyword search for the drawing's document number:

| If you want the drawing for this package | Then use this document number |
|---|---|
| 44-pin LGA | 98ASA00239D |
| 64-pin LQFP | 98ASS23234W |
| 100-pin LQFP | 98ASS23308W |

# 8 Pinout

**NOTE**

VSS also connects to flag on 44 LGA.

## 8.1 KM Signal multiplexing and pin assignments

| 100 QFP | 64 QFP | 44 LGA | DEFAULT | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 | 1 | — | Disabled | LCD23 | PTA0 | | | | | | |
| 2 | 2 | — | Disabled | LCD24 | PTA1 | | | | | | |
| 3 | 3 | — | Disabled | LCD25 | PTA2 | | | | | | |
| 4 | — | — | Disabled | LCD26 | PTA3 | | | | | | |
| 5 | 4 | 1 | NMI_B | LCD27 | PTA4 | LLWU_P15 | | | | | NMI_B |
| 6 | 5 | 2 | Disabled | LCD28 | PTA5 | CMP0OUT | | | | | |
| 7 | 6 | 3 | Disabled | LCD29 | PTA6 | XBAR_IN0 | LLWU_P14 | | | | |
| 8 | 7 | 4 | Disabled | LCD30 | PTA7 | XBAR_OUT0 | | | | | |
| 9 | — | — | Disabled | LCD31 | PTB0 | | | | | | |
| 10 | 8 | 5 | VDD | VDD | | | | | | | |
| 11 | 9 | 6 | VSS | VSS | | | | | | | |
| 12 | — | — | Disabled | LCD32 | PTB1 | | | | | | |
| 13 | — | — | Disabled | LCD33 | PTB2 | | | | | | |
| 14 | — | — | Disabled | LCD34 | PTB3 | | | | | | |
| 15 | — | — | Disabled | LCD35 | PTB4 | | | | | | |
| 16 | — | — | Disabled | LCD36 | PTB5 | | | | | | |
| 17 | — | — | Disabled | LCD37/ CMP1P0 | PTB6 | | | | | | |

| 100 QFP | 64 QFP | 44 LGA | DEFAULT | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 18 | 10 | — | Disabled | LCD38 | PTB7 | AFE_CLK | | | | | |
| 19 | 11 | — | Disabled | LCD39 | PTC0 | UART3_RTS | XBAR_IN1 | | | | |
| 20 | 12 | — | Disabled | LCD40/ CMP1P1 | PTC1 | UART3_CTS | | | | | |
| 21 | 13 | — | Disabled | LCD41 | PTC2 | UART3_TxD | XBAR_OUT1 | | | | |
| 22 | 14 | — | Disabled | LCD42/ CMP0P3 | PTC3 | UART3_RxD | LLWU_P13 | | | | |
| 23 | — | — | Disabled | LCD43 | PTC4 | | | | | | |
| 24 | 15 | 7 | VBAT | VBAT | | | | | | | |
| 25 | 16 | 8 | XTAL32K | XTAL32K | | | | | | | |
| 26 | 17 | 9 | EXTAL32K | EXTAL32K | | | | | | | |
| 27 | 18 | 10 | VSS | VSS | | | | | | | |
| 28 | — | — | TAMPER2 | TAMPER2 | | | | | | | |
| 29 | — | — | TAMPER1 | TAMPER1 | | | | | | | |
| 30 | 19 | 11 | TAMPER0 | TAMPER0 | | | | | | | |
| 31 | 20 | 12 | VDDA | VDDA | | | | | | | |
| 32 | 21 | 13 | VSSA | VSSA | | | | | | | |
| 33 | 22 | 14 | SDADP0 | SDADP0 | | | | | | | |
| 34 | 23 | 15 | SDADM0 | SDADM0 | | | | | | | |
| 35 | 24 | 16 | SDADP1 | SDADP1 | | | | | | | |
| 36 | 25 | 17 | SDADM1 | SDADM1 | | | | | | | |
| 37 | 26 | 18 | VREFH | VREFH | | | | | | | |
| 38 | 27 | 19 | VREFL | VREFL | | | | | | | |
| 39 | 28 | 20 | SDADP2/ CMP1P2 | SDADP2/ CMP1P2 | | | | | | | |
| 40 | 29 | 21 | SDADM2/ CMP1P3 | SDADM2/ CMP1P3 | | | | | | | |
| 41 | 30 | 22 | VREF | VREF | | | | | | | |
| 42 | — | 24 | SDADP3/ CMP1P4 | SDADP3/ CMP1P4 | | | | | | | |
| 43 | — | 23 | SDADM3/ CMP1P5 | SDADM3/ CMP1P5 | | | | | | | |
| 44 | — | — | Disabled | AD0 | PTC5 | UART0_RTS | LLWU_P12 | | | | |
| 45 | — | — | Disabled | AD1 | PTC6 | UART0_CTS | TMR_1 | | | | |
| 46 | — | — | Disabled | AD2 | PTC7 | UART0_TxD | XBAR_OUT2 | | | | |
| 47 | — | — | Disabled | CMP0P0 | PTD0 | UART0_RxD | XBAR_IN2 | LLWU_P11 | | | |
| 48 | 31 | — | Disabled | | PTD1 | UART1_TxD | SPI0_SS_B | XBAR_OUT3 | TMR_3 | | |
| 49 | 32 | — | Disabled | CMP0P1 | PTD2 | UART1_RxD | SPI0_SCK | XBAR_IN3 | LLWU_P10 | | |
| 50 | 33 | — | Disabled | | PTD3 | UART1_CTS | SPI0_MOSI | | | | |
| 51 | 34 | — | Disabled | AD3 | PTD4 | UART1_RTS | SPI0_MISO | LLWU_P9 | | | |
| 52 | — | — | Disabled | AD4 | PTD5 | LPTMR2 | TMR_0 | UART3_CTS | | | |
| 53 | — | — | Disabled | AD5 | PTD6 | LPTMR1 | CMP1OUT | UART3_RTS | LLWU_P8 | | |
| 54 | — | — | Disabled | CMP0P4 | PTD7 | I2C0_SCL | XBAR_IN4 | UART3_RxD | LLWU_P7 | | |

| 100 QFP | 64 QFP | 44 LGA | DEFAULT | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 55 | — | — | Disabled | | PTE0 | I2C0_SDA | XBAR_OUT4 | UART3_TxD | CLKOUT | | |
| 56 | 35 | 25 | RESET_B | | PTE1 | | | | | | RESET_B |
| 57 | — | 26 | EXTAL1 | EXTAL1 | PTE2 | EWM_IN | XBAR_IN6 | I2C1_SDA | | | |
| 58 | — | 27 | XTAL1 | XTAL1 | PTE3 | EWM_OUT | AFE_CLK | I2C1_SCL | | | |
| 59 | 36 | 28 | VSS | VSS | | | | | | | |
| 60 | — | 29 | SAR_VSSA | SAR_VSSA | | | | | | | |
| 61 | — | 30 | SAR_VDDA | SAR_VDDA | | | | | | | |
| 62 | 37 | 31 | VDD | VDD | | | | | | | |
| 63 | — | — | Disabled | | PTE4 | LPTMR0 | UART2_CTS | EWM_IN | | | |
| 64 | — | — | Disabled | | PTE5 | TMR_3 | UART2_RTS | EWM_OUT | LLWU_P6 | | |
| 65 | 38 | 32 | SWD_IO | CMP0P2 | PTE6 | XBAR_IN5 | UART2_RxD | LLWU_P5 | | | SWD_IO |
| 66 | 39 | 33 | SWD_CLK | AD6 | PTE7 | XBAR_OUT5 | UART2_TxD | | | | SWD_CLK |
| 67 | 40 | — | Disabled | AD7 | PTF0 | RTCCLKOUT | TMR_2 | CMP0OUT | | | |
| 68 | 41 | 34 | Disabled | LCD0/ AD8 | PTF1 | TMR_0 | XBAR_OUT6 | | | | |
| 69 | 42 | 35 | Disabled | LCD1/ AD9 | PTF2 | CMP1OUT | RTCCLKOUT | | | | |
| 70 | 43 | — | Disabled | LCD2 | PTF3 | SPI1_SS_B | LPTMR1 | UART0_RxD | | | |
| 71 | 44 | — | Disabled | LCD3 | PTF4 | SPI1_SCK | LPTMR0 | UART0_TxD | | | |
| 72 | 45 | — | Disabled | LCD4 | PTF5 | SPI1_MISO | I2C1_SCL | LLWU_P4 | | | |
| 73 | 46 | — | Disabled | LCD5 | PTF6 | SPI1_MOSI | I2C1_SDA | LLWU_P3 | | | |
| 74 | 47 | — | Disabled | LCD6 | PTF7 | TMR_2 | CLKOUT | | | | |
| 75 | 48 | — | Disabled | LCD7 | PTG0 | TMR_1 | LPTMR2 | | | | |
| 76 | 49 | 36 | Disabled | LCD8/ AD10 | PTG1 | LLWU_P2 | LPTMR0 | | | | |
| 77 | 50 | 37 | Disabled | LCD9/ AD11 | PTG2 | SPI0_SS_B | LLWU_P1 | | | | |
| 78 | 51 | 38 | Disabled | LCD10 | PTG3 | SPI0_SCK | I2C0_SCL | | | | |
| 79 | 52 | 39 | Disabled | LCD11 | PTG4 | SPI0_MOSI | I2C0_SDA | | | | |
| 80 | 53 | 40 | Disabled | LCD12 | PTG5 | SPI0_MISO | LPTMR1 | | | | |
| 81 | 54 | — | Disabled | LCD13 | PTG6 | LLWU_P0 | LPTMR2 | | | | |
| 82 | — | — | Disabled | LCD14 | PTG7 | | | | | | |
| 83 | — | — | Disabled | LCD15 | PTH0 | | | | | | |
| 84 | — | — | Disabled | LCD16 | PTH1 | | | | | | |
| 85 | — | — | Disabled | LCD17 | PTH2 | | | | | | |
| 86 | — | — | Disabled | LCD18 | PTH3 | | | | | | |
| 87 | — | — | Disabled | LCD19 | PTH4 | | | | | | |
| 88 | — | — | Disabled | LCD20 | PTH5 | | | | | | |
| 89 | — | 41 | Disabled | | PTH6 | UART1_CTS | SPI1_SS_B | XBAR_IN7 | | | |
| 90 | — | 42 | Disabled | | PTH7 | UART1_RTS | SPI1_SCK | XBAR_OUT7 | | | |
| 91 | 55 | 43 | Disabled | CMP0P5 | PTI0 | UART1_RxD | XBAR_IN8 | SPI1_MISO | SPI1_MOSI | | |
| 92 | 56 | 44 | Disabled | | PTI1 | UART1_TxD | XBAR_OUT8 | SPI1_MOSI | SPI1_MISO | | |

| 100 QFP | 64 QFP | 44 LGA | DEFAULT | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 93 | 57 | — | Disabled | LCD21 | PTI2 | | | | | | |
| 94 | 58 | — | Disabled | LCD22 | PTI3 | | | | | | |
| 95 | 59 | — | VSS | VSS | | | | | | | |
| 96 | 60 | — | VLL3 | VLL3 | | | | | | | |
| 97 | 61 | — | VLL2 | VLL2 | | | | | | | |
| 98 | 62 | — | VLL1 | VLL1 | | | | | | | |
| 99 | 63 | — | VCAP2 | VCAP2 | | | | | | | |
| 100 | 64 | — | VCAP1 | VCAP1 | | | | | | | |

## 8.2 KM Family Pinouts

### 8.2.1 100-pin LQFP

The following figure represents the KM 100 LQFP pinouts:

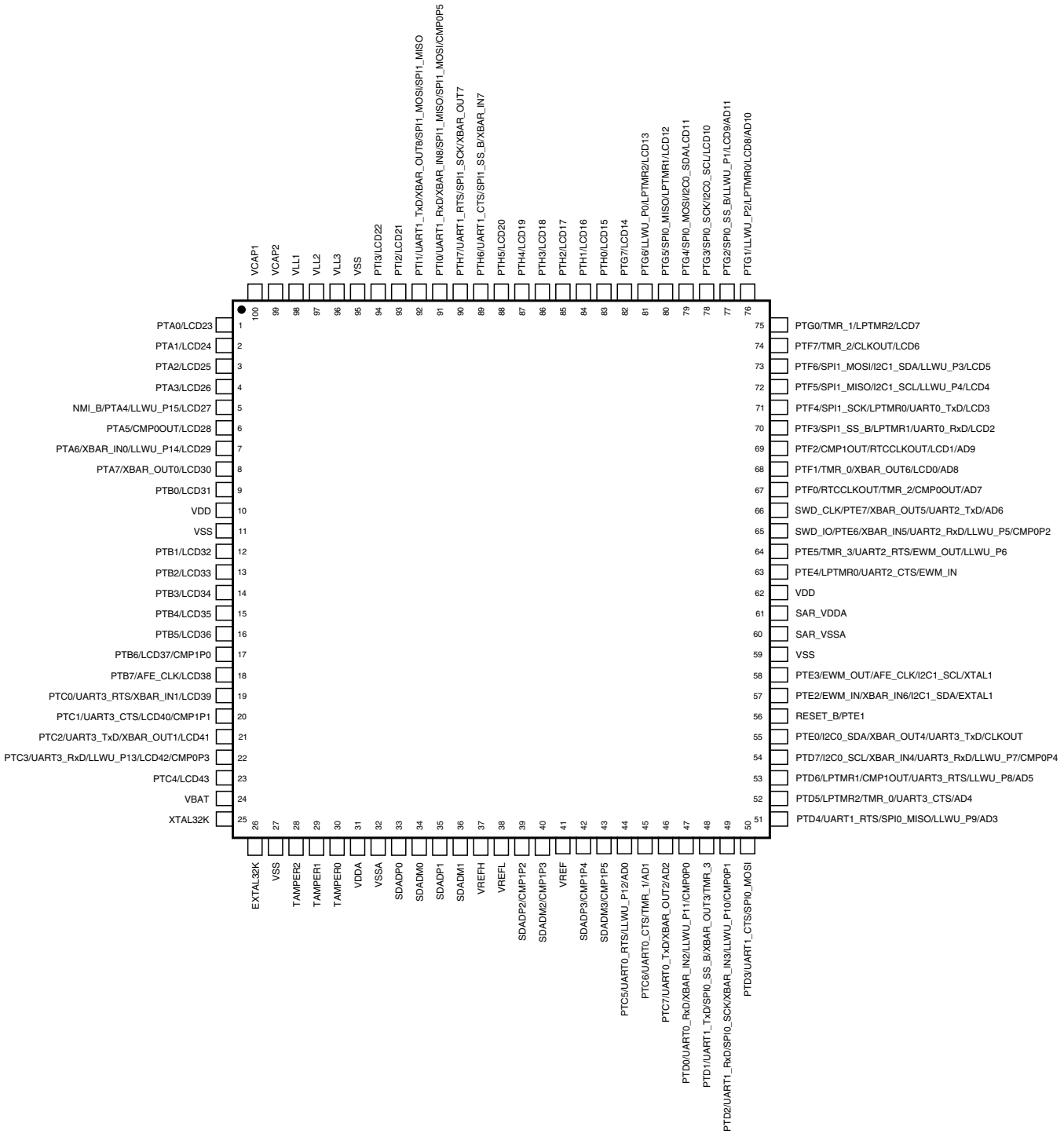



**Figure 6. 100-pin LQFP Pinout Diagram**

## 8.2.2 64-pin LQFP

The following figure represents 64-pin LQFP pinouts:

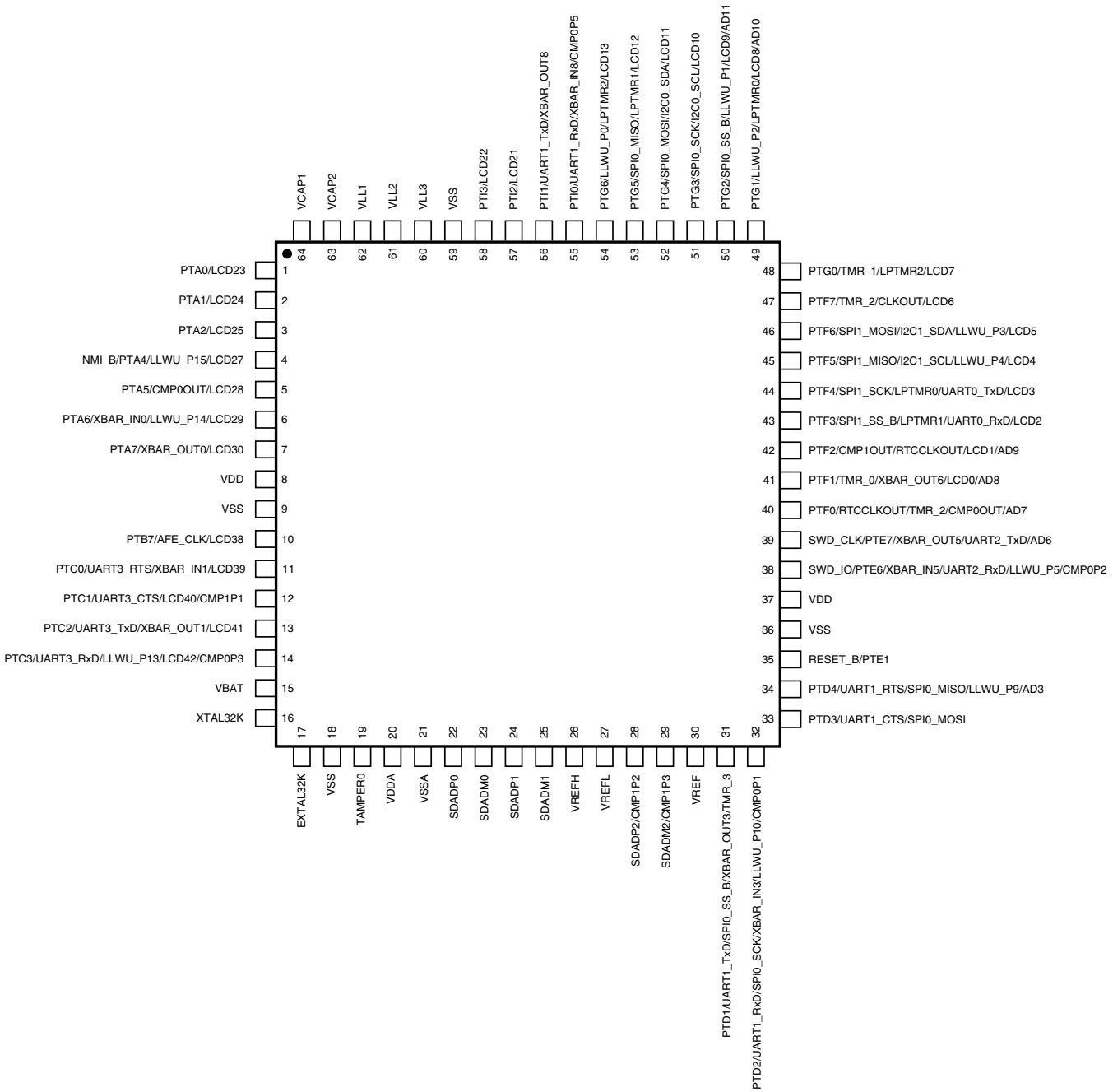



**Figure 7. 64-pin LQFP Pinout Diagram**

## 8.2.3 44-pin LGA

The following figure represents44-pin LGA pinouts:

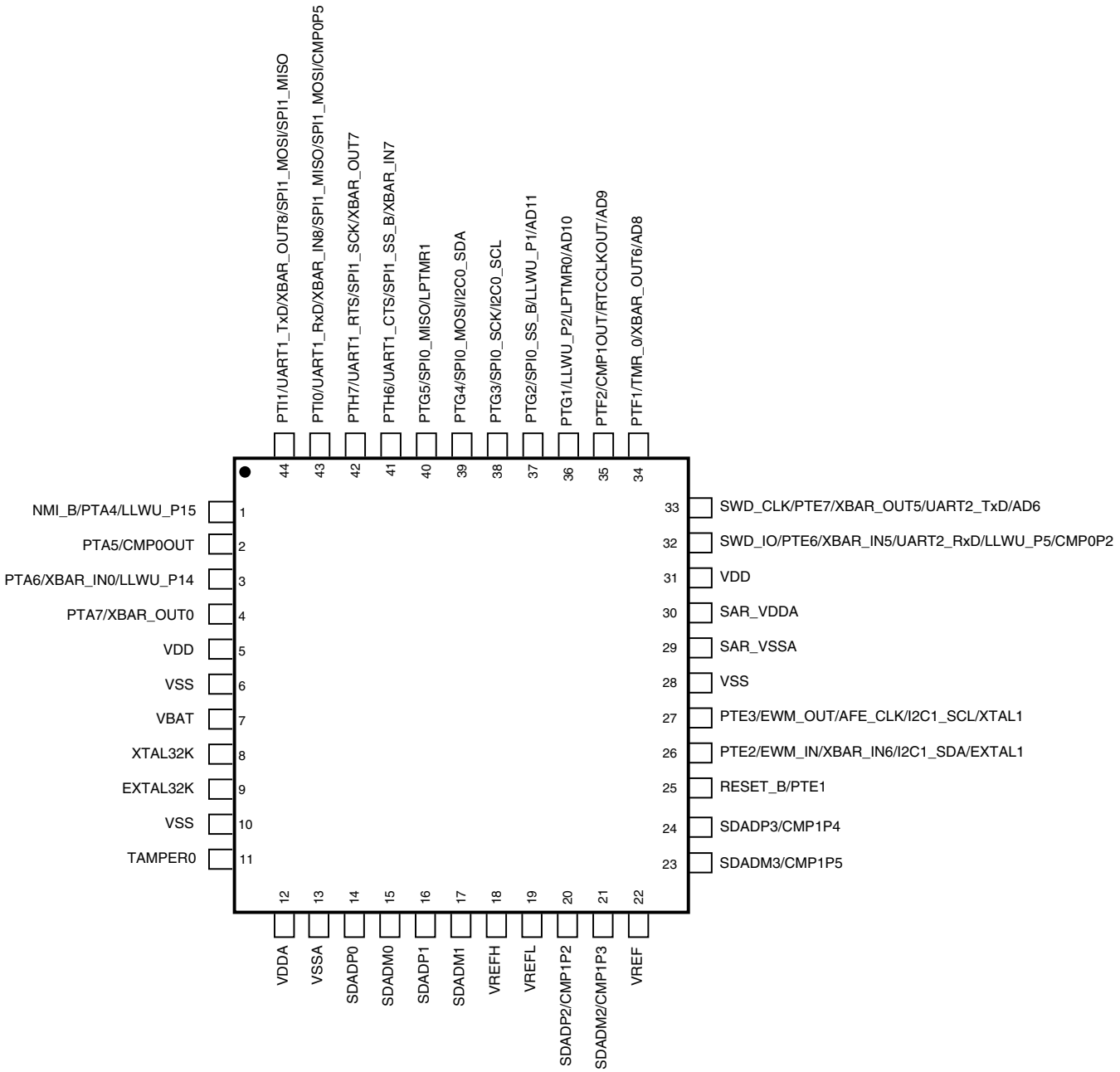



**Figure 8. 44-pin LGA Pinout Diagram**

**NOTE**

VSS also connects to flag on 44 LGA.

# 9 Revision History

The following table provides a revision history for this document.

## Table 41. Revision History

| Rev. No. | Date | Substantial Changes |
|---|---|---|
| Rev1 | 10/2012 | Initial release |
| Rev2 | 01/2013 | Updated part numbers<br>Updated Table: Power mode transition operating behaviors<br>Updated Table: Power consumption operating behaviors. Included readings for temperature - 40 °C, 25 °C, and 85 °C<br>Updated AFE Modulator clock maximum value in table “Device clock specifications”<br>Updated Table: General switching specifications<br>Updated Table: Thermal operating requirements<br>Updated Table: SWD switching specifications<br>Added Table: AFE (Analog Frontend ) Switching characteristics<br>Updated Table: Oscillator DC electrical specifications<br>Updated Table: ΣΔ ADC + PGA specifications<br>Under section SPI switching specification,<br>• Table SPI timing renamed to SPI switching characteristics at 2.7 V ( 2.7 - 3.6)<br>• Modified row: “Data Hold Time (inputs, tHI)” to “Input Data Hold Time (inputs, tHI)”<br>• Modified row: “Data valid time (after SCK edge, tDVO)” to “Data Valid Out Time (after SCK edge, tDVO)”<br>Added table: SPI Switching characteristics at 1.7V (1.7 - 3.6V)<br>NOTE added to KM Signal Multiplexing and Pin Assignments topic |
| Rev3 | 04/2013 | Updated orderable part numbers<br>Updated Table: ESD handling ratings<br>• Add new row: Electrostatic discharge voltage, charged-device mode<br>Updated Table: Voltage and current operating behaviors<br>Updated Table: Power consumption operating behaviors<br>Updated "Inputs, tSUI" row in Table: SWD switching characteristics at 2.7 V (2.7 - 3.6 V)<br>Updated "Inputs, tSUI" row in Table: AFE switching characteristics (1.7 V - 3.6 V)<br>Updated "Supply voltage" minimum value in table: Voltage reference electrical specifications<br>Added table: OD cells in SPI Switching specification<br>Updated Table: VREF full-range operating behaviors<br>Updated Table: ΣΔ ADC + PGA specifications<br>Updated Table: ADC standalone specifications |

*Table continues on the next page...*

## Table 41. Revision History (continued)

| Rev. No. | Date | Substantial Changes |
|---|---|---|
| Rev4 | 07/2013 | Editorial changes through out the document.<br><br>Values of table "Power mode transition operating behaviors" updated.<br><br>In table "Power consumption operating behaviors":<br>• Row $I_{DD_RUN}$ value updated<br>• Row $I_{DD_WAIT}$ value updated<br>• Row $I_{DD_VLPR}$ value updated<br>• Row $I_{DD_VLPW}$ value updated<br>• Row $I_{DD_STOP}$ value updated<br>• Row $I_{DD_VLPS}$ value updated<br>• Row $I_{DD_VLLS3}$ value updated<br>• Row $I_{DD_VLLS2}$ value updated<br>• Row $I_{DD_VLLS1}$ value updated<br>• Row $I_{DD_VLLS0}$ value updated<br>• Row $I_{DD_VBAT}$ value updated<br>• New row "$I_{DD_VLLS0}$ with POR enabled" added.<br><br>Values of table "General switching specifications" updated.<br><br>In table "VREF full-range operating behaviors":<br>• Row $V_{tdrift}$: value updated and footnote added.<br><br>In table "LCD electricals":<br>• Row $I_{RBIAS}$: values updated. |
| Rev5 | 10/2013 | Table: Obtaining package dimensions updated |
| Rev6 | 11/2013 | Updated Section Fields:<br>• Row: Temperature range values updated.<br><br>Updated Table: Power consumption operating behaviors |
| Rev7 | 1/2014 | • Table: Power consumption operating behaviors<br>  • All rows with temperature 110 °C updated to 105 °C<br>  • Footnote 9 updated: An external power switch for VBAT should be present on board to have better battery life and keep VBAT pin powered in all conditions. There is no internal power switch in RTC.<br>  • Row $I_{DD_VLPR}$: Minimum value updated<br>  • Row $I_{DD_VLLS1}$: Typ value updated<br>  • Row $I_{DD_VLLS0}$ with POR circuit disabled: Typ value updated<br>  • Row $I_{DD_VLLS0}$ with POR circuit enabled: Typ value updated<br>• Table: EMC radiated emissions operating behaviors<br>  • All TBD updated<br>  • Footnote 2: $f_{osc}$ value updated to 10 MHz<br>• Table: ADC + PGA specifications<br>  • Row CMMR: $V_{id}$ value updated<br>• Table: ADC standalone specifications<br>  • Row CMMR: $V_{id}$ value updated |

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